

Spatial Resolved EUV Spectrum of EUV-Lamp

XUV Research with Compact DPP and LPP Laboratory Sources: Complementary to Beamlines and Large Scale Industrial Tools

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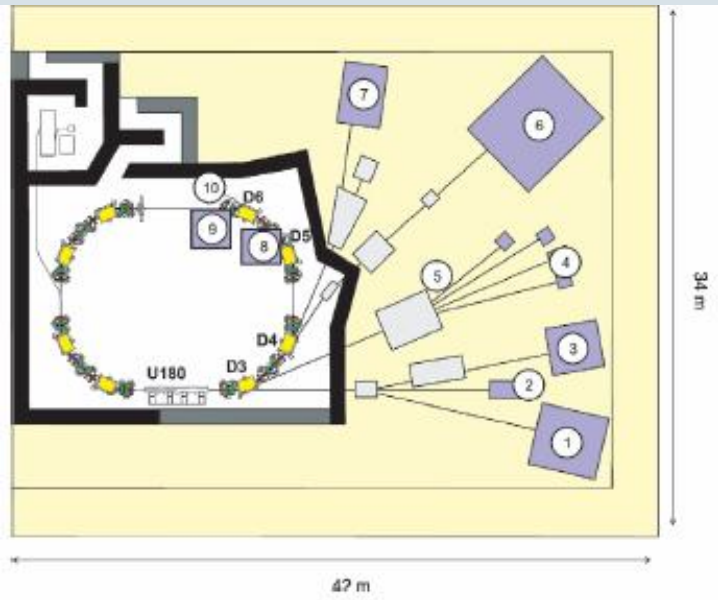
RWTH Aachen, Chair for
Experimental Physics of EUV

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From Storage Ring to Lab Source

Synchrotron based Metrology



EUV SCANNER



Lab Metrology Sources



Solving any task with any process requires:

- Analyze top-level requirements for applied process and target of use (Reflectometry (NI, GI), Transmission, Scatter, Irradiation, Interference, etc.)
- Find effective solution of EUV-Source, collection, SPF, optical scheme, sample handling geometry, monitoring and signal detection
- Integrate with high quality periphery and components (vacuum, cleanliness, vibration, safety, operation)

EUV Lab sources are the one key element

In contrast to HVM sources, metrology sources are available in both general forms: DPP & LPP, which allows to select for the required features and can even be selected / tuned to special demands (wavelength range, bandwidth, spectral purity, interaction area (sample), spatial distribution etc.)

Easy Source – Tool vacuum and automation integration has been demonstrated.

For real industrial and tool use optimization with respect to spectrum, collection geometry, effective debris mitigation and monitoring is designed on case to case basis.

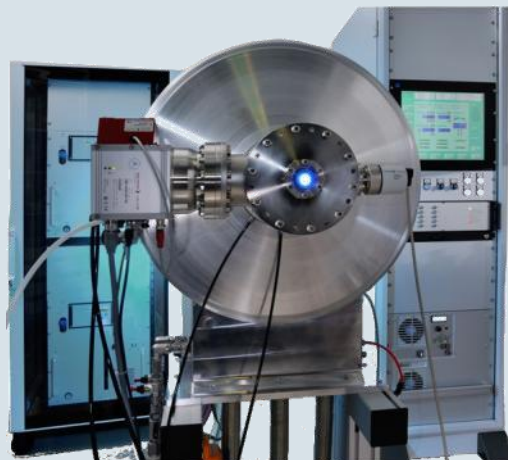
Portfolio of EUV Metrology Sources

Demands: Power, Brightness, Debris-free, Stability, Cleanliness, Integration

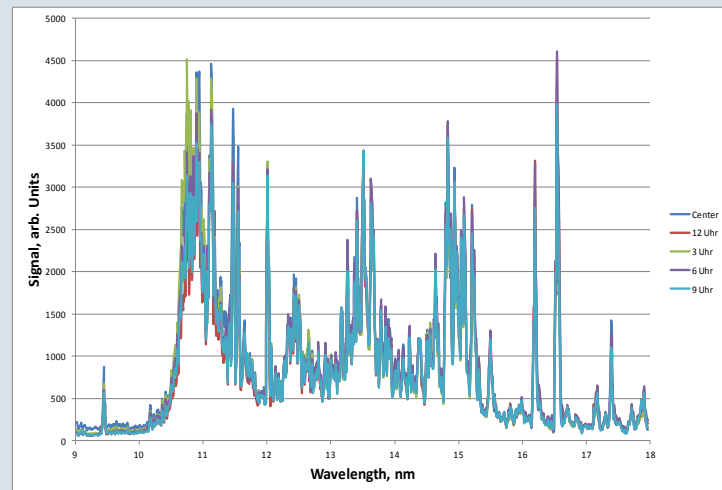
Discharge Produced:



EUV-Lamp < 1 W EUV inband



EUV-Source > 20 W EUV inband



DPP spectrum of Xenon EUV-Lamp under different angles

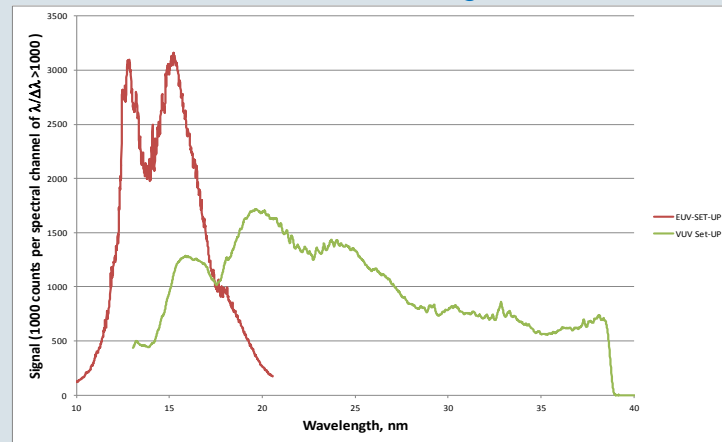
Laser Produced:



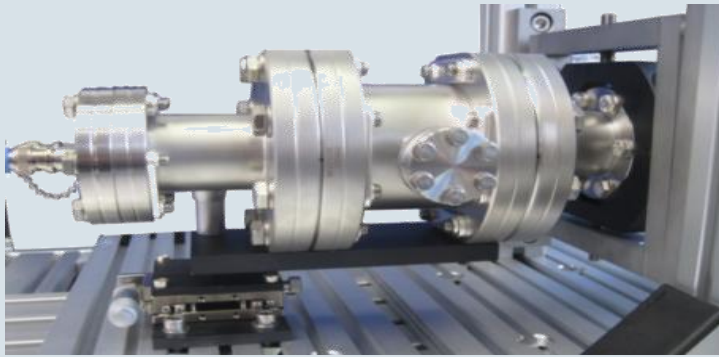
LPP < 5 mW EUV inband for spectr.



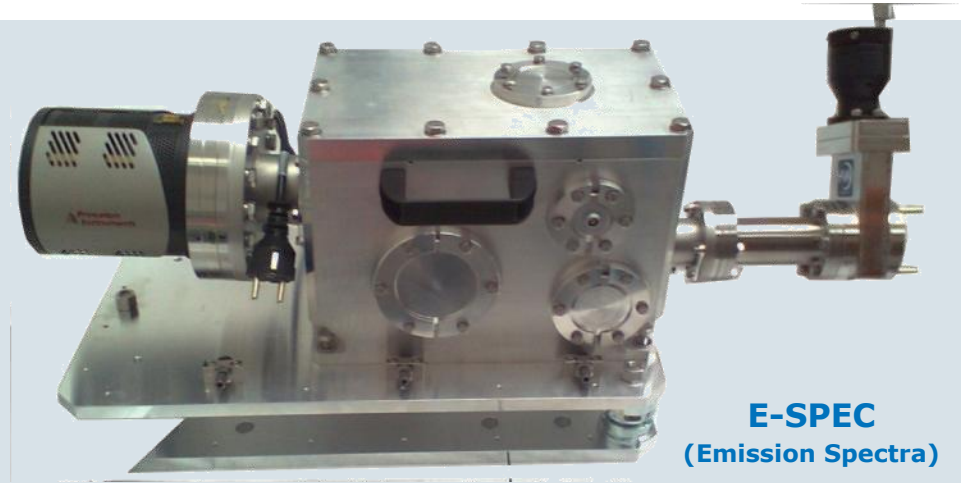
HB-LPP > 200 W/mm²/sr inband



LPP source gold emission



E-MON (inband Pulse and Power)



E-SPEC
(Emission Spectra)

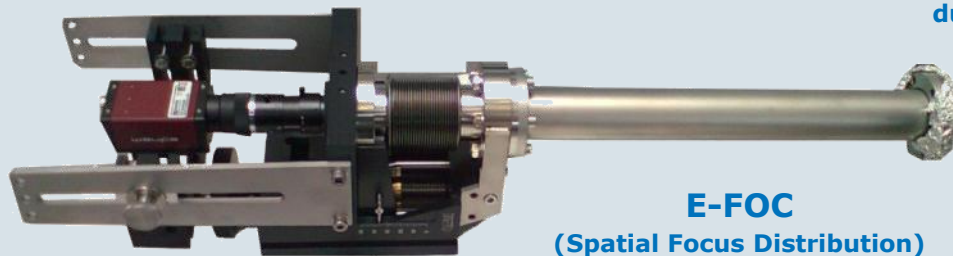
PTB Calibration Support is appreciated !



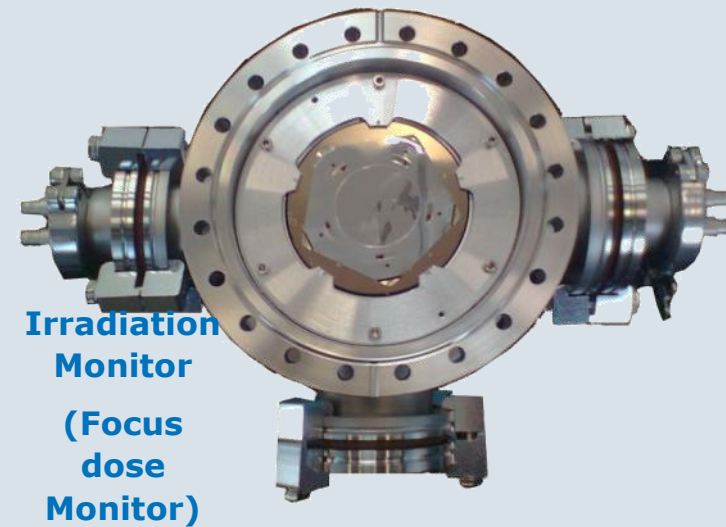
E-CAM
(Spatial Emission Distribution)



E-Diode
(Pulse duration)

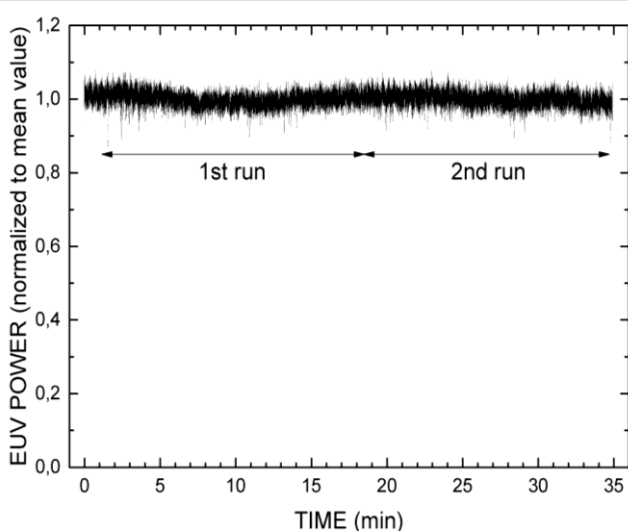


E-FOC
(Spatial Focus Distribution)

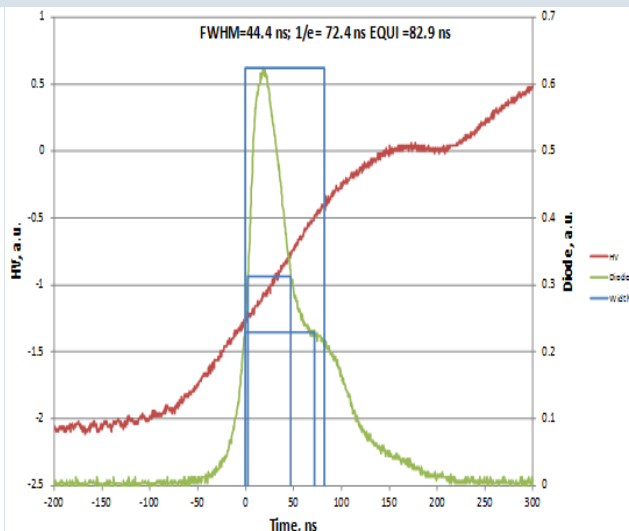


Irradiation Monitor
(Focus dose Monitor)

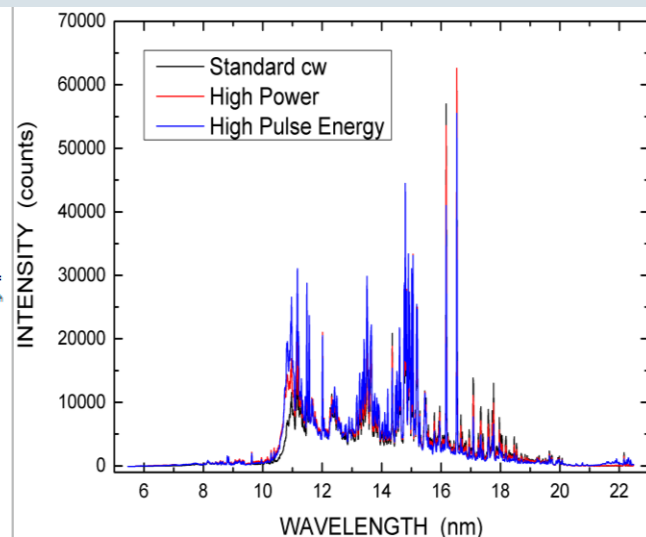
Scope of Source Qualification: Power, Pulse, Spectrum, Size and Statistics of All



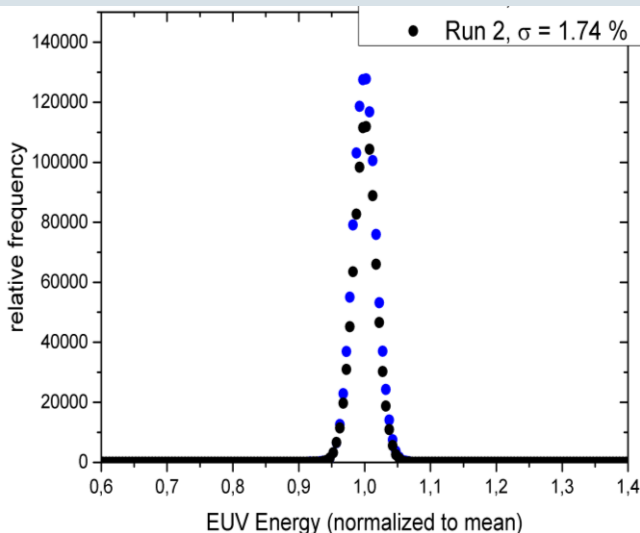
EUV inband Power: E-MON



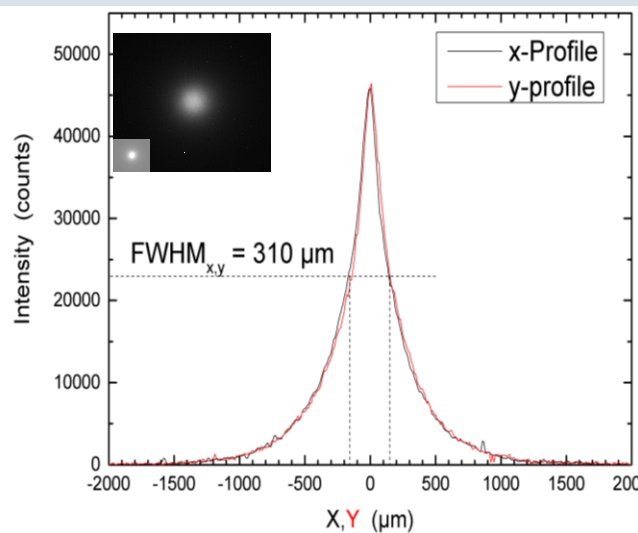
EUV Pulse Duration



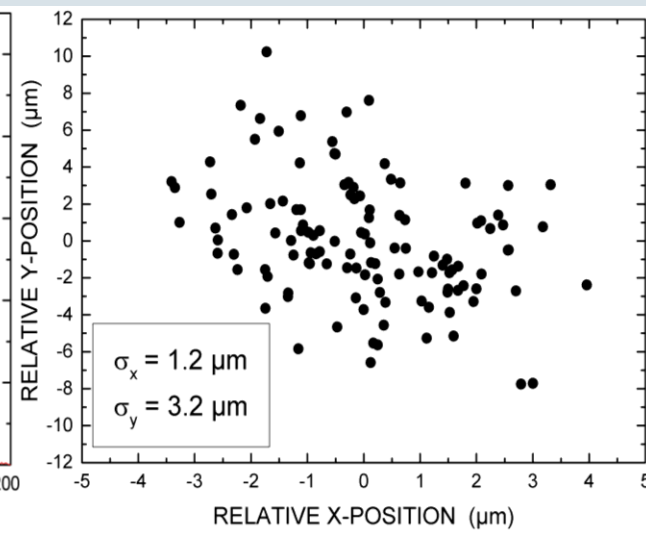
EUV Spectrum: E-SPEC



Pulse Statistics



Source Size



Position Stability

EUV Mask Reflectometry: EUV-MBR

Top Level Task

Measure spectral reflectance of multilayer and absorbers with high precision and accuracy (x* SEMI masks) under 6° AOI with high throughput

Experimental Targets

Spectral Reflectometry at 12.5-14.5 nm.

Reproducibility of $R_{\max} < 0.2\%$ abs and $CWL_{50} < 5\text{ pm}$!

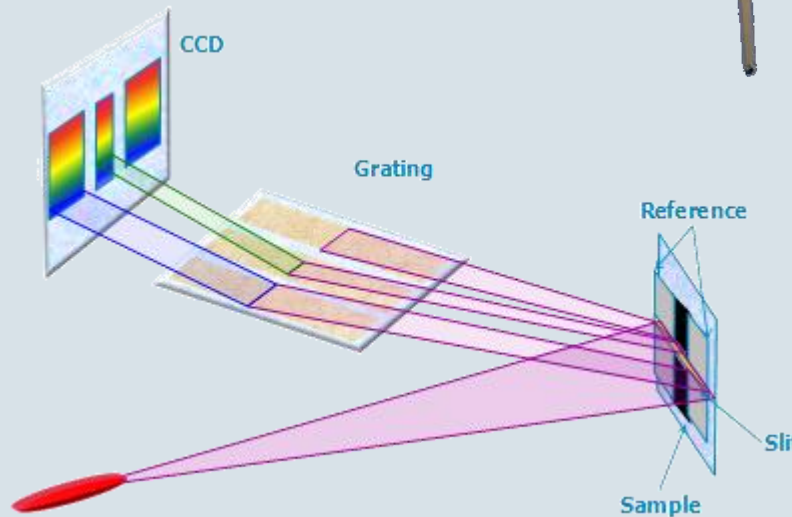
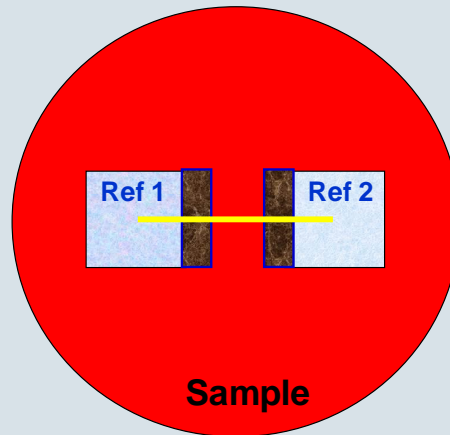
Solving Concept

Polychromatic reflectometry relative to reference with $\Delta\lambda/\lambda > 2000$ resolution

Immanent wavelength calibration with NIST Xe lines

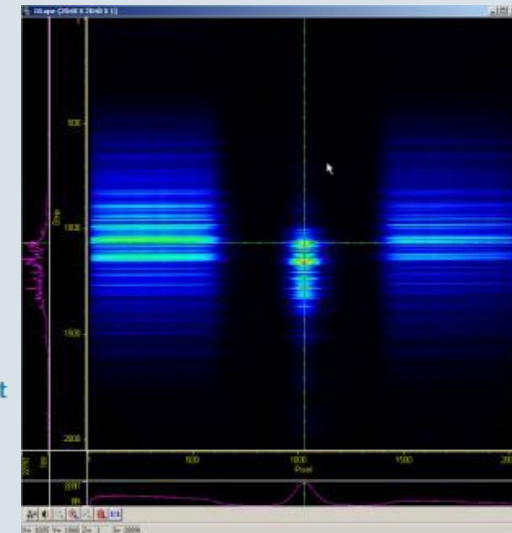
Broadband EUV Spectrum of $< 300\text{ mW}/2\text{p sr}$ i.b.

Reliable and stable

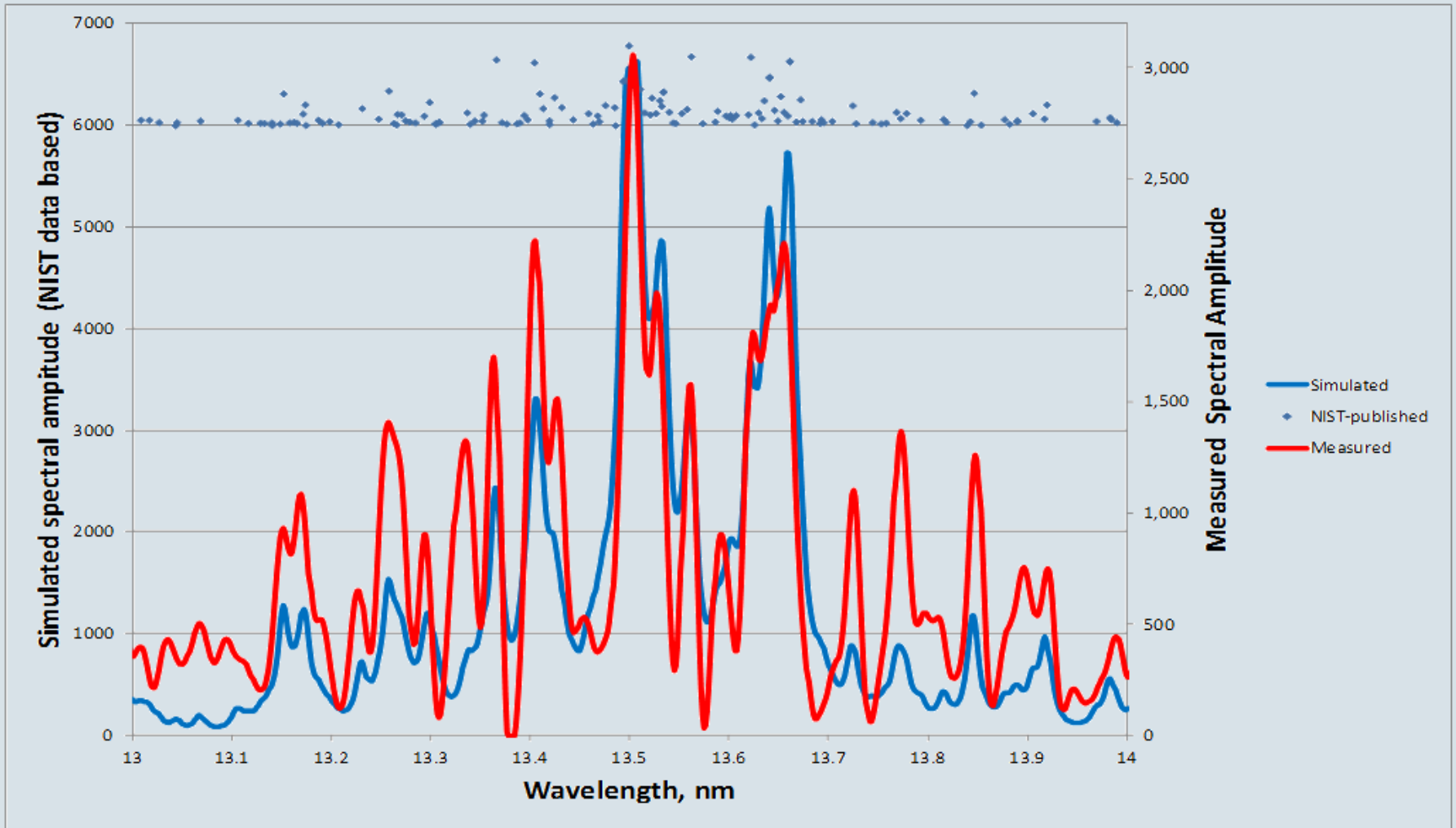


Performance:

Spot: $250 \times 100\ \mu\text{m}^2$; result in 20 seconds; precision σ : 0.2 %, 1 pm



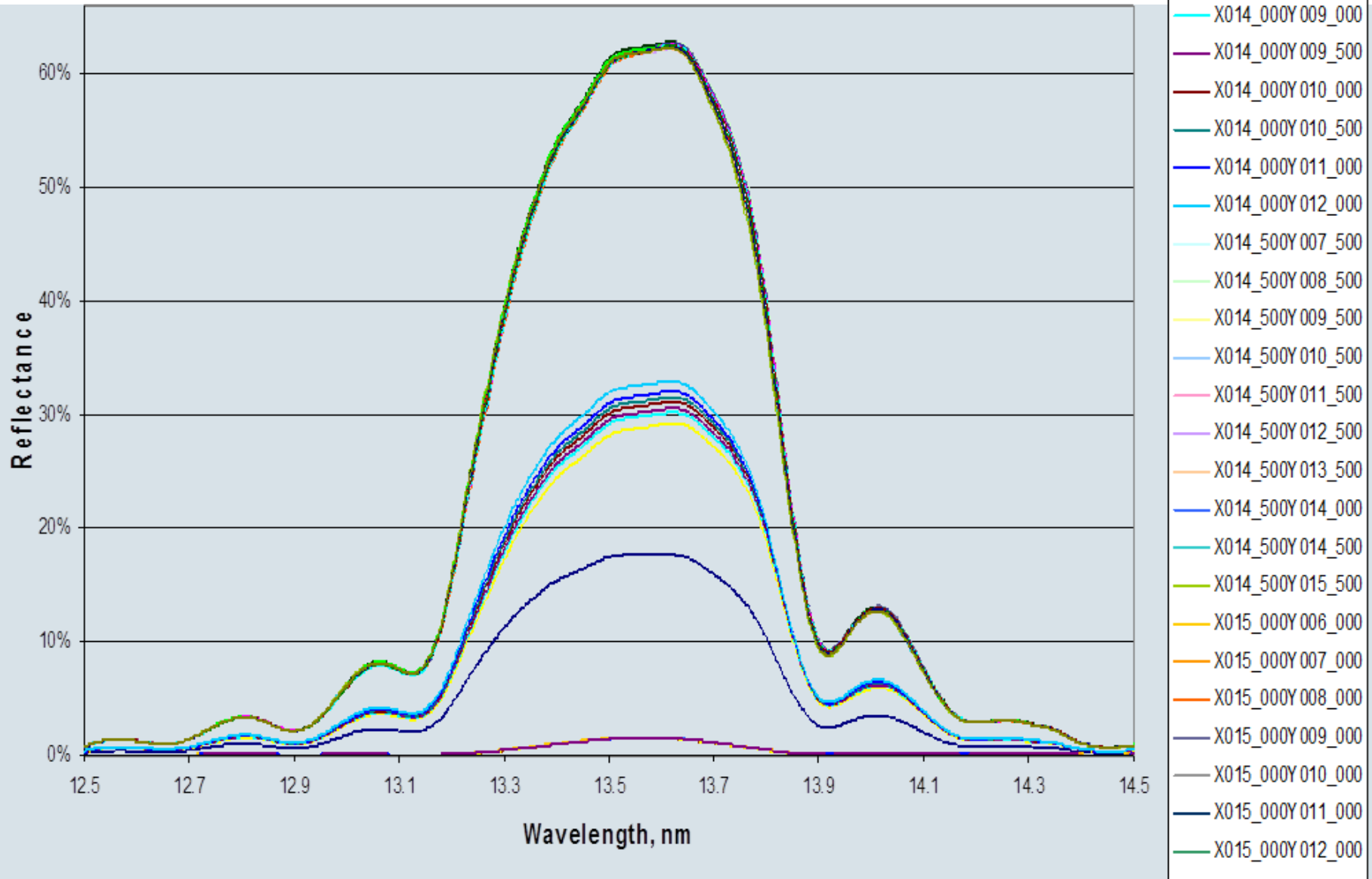
Special Development: Immanent WL Calibration with by NIST Xe Lines



→ Accuracy better one spectral channel

→ MBR: < 1.6 nm; XUV-SPM < 8 pm @ 13.5 pm ($\lambda/\Delta\lambda > 8,000$ resp. 1,500)

Example: Stepping Measurement over Structured Mask delivers linear superimposed results.



XUV Spectrophotometry: XUV-SPM

Top Level Task

R&D grade spectral photometry of arbitrary samples (also gases and curved) in arbitrary geometry in spectral range from (2) 8-40 nm

Experimental Target

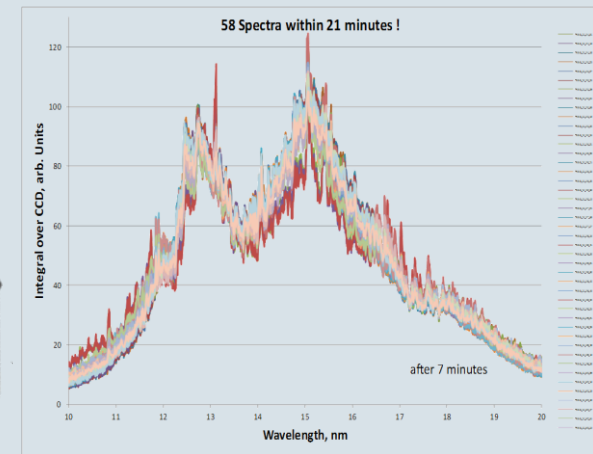
Spectral characterization of samples under arbitrary AOI: 0° to 85°

Reproducibility of < 0.5 % abs. and < 25 pm !

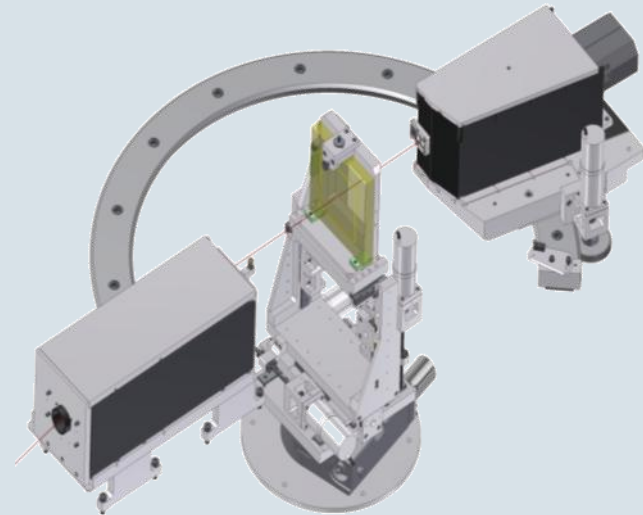
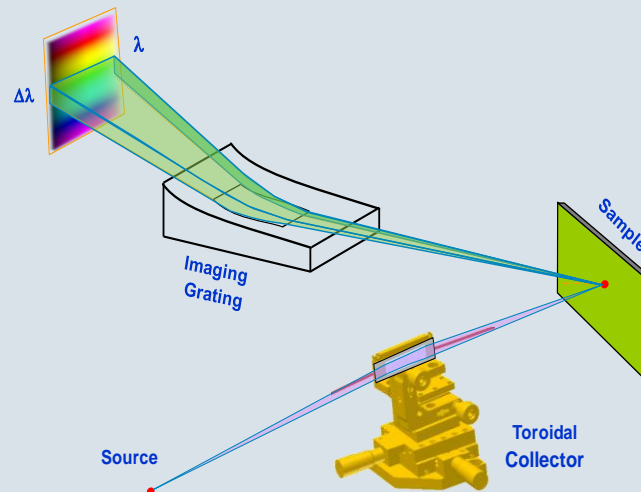
Solving Concept

Demagnify source onto sample
Dose monitored; polychromatic spectrograph with $\Delta\lambda/\lambda > 500$
Immanent Xe WL calibration

Low power small size broadband XUV source
→ gold LPP source



LPP < 5 mW EUV i.b. for spectroscopy

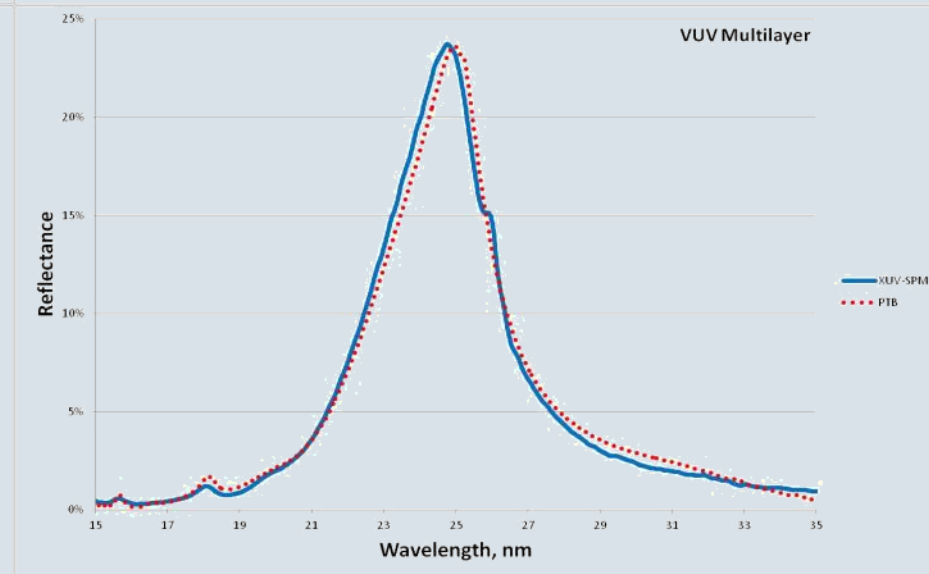
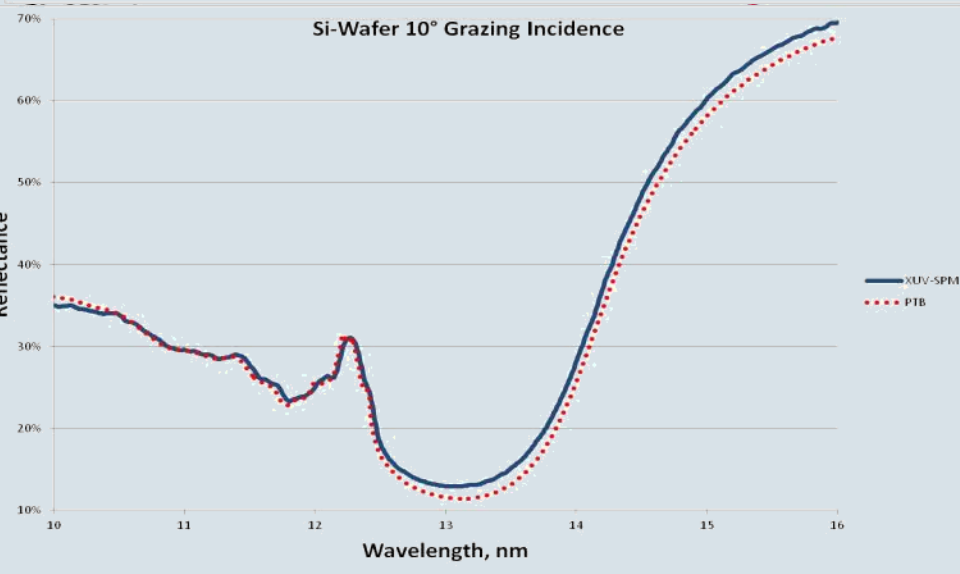
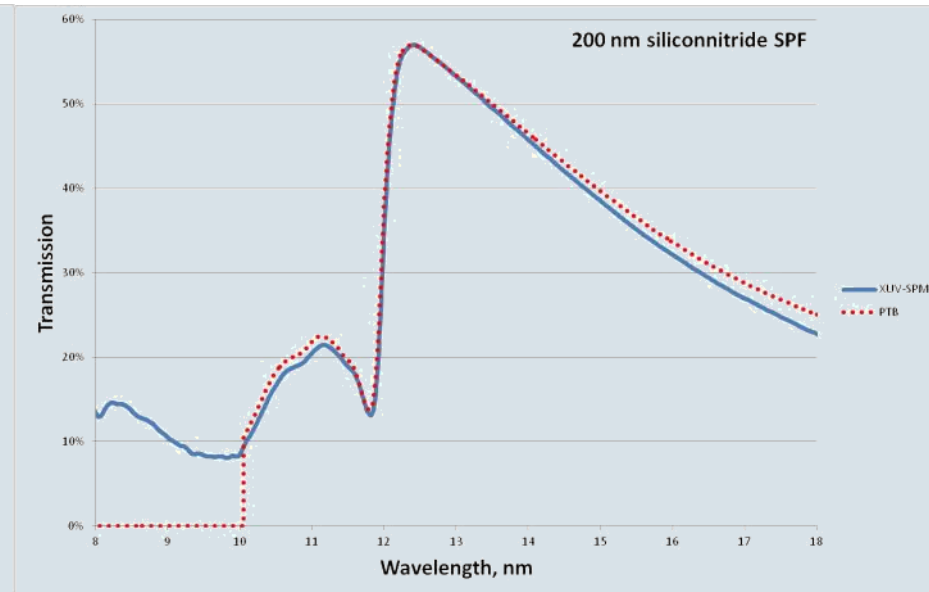
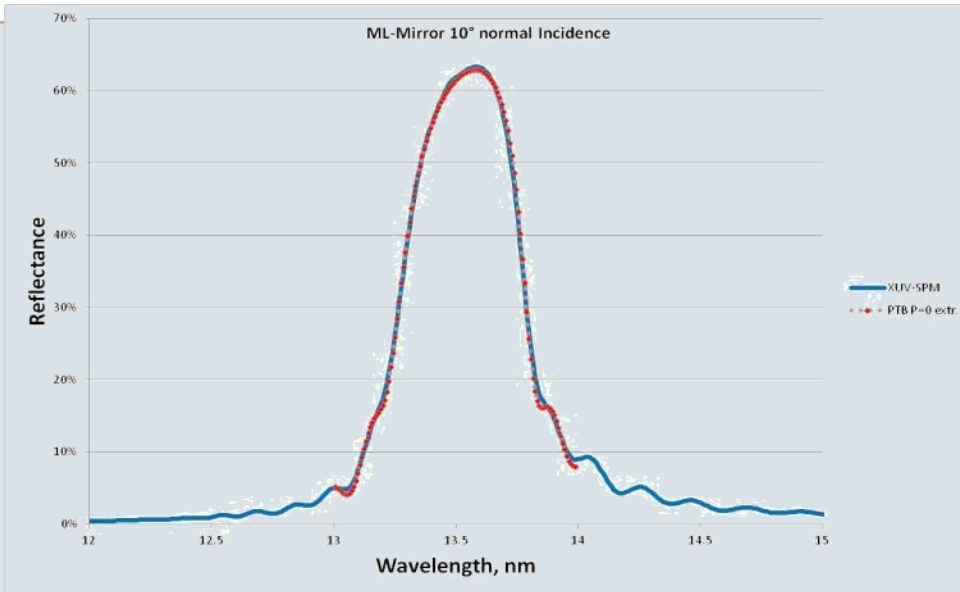


Performance:

$\varnothing \approx 50 \mu\text{m}$; one spectrum in 30 seconds; precision σ : 0.5 %, 10 pm

XUV-SPM: Flexibility

GI & NI Reflection, Transmission, VUV, Gases



XUV-SPM Accuracy: Influence of Polarization to be accounted for

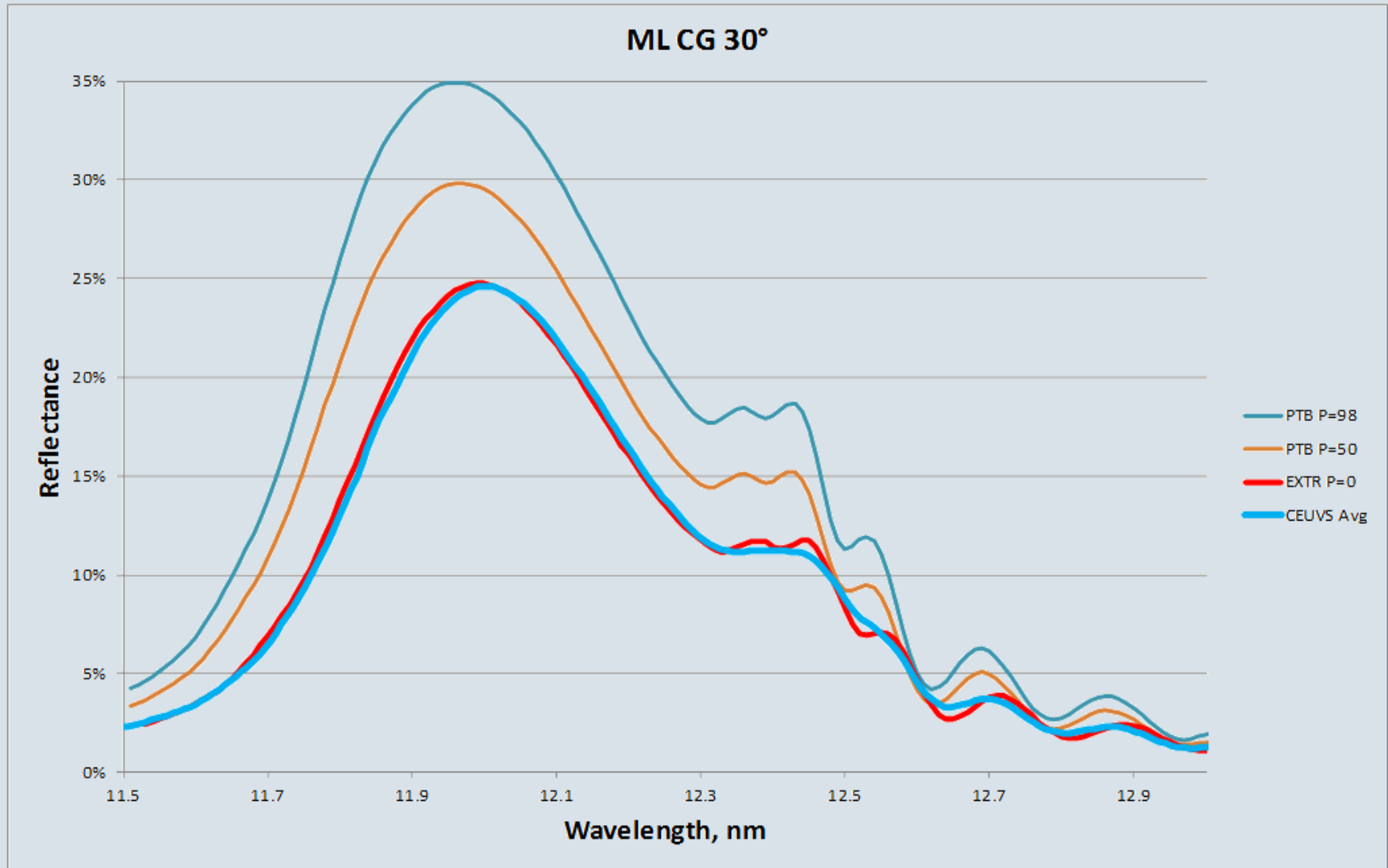
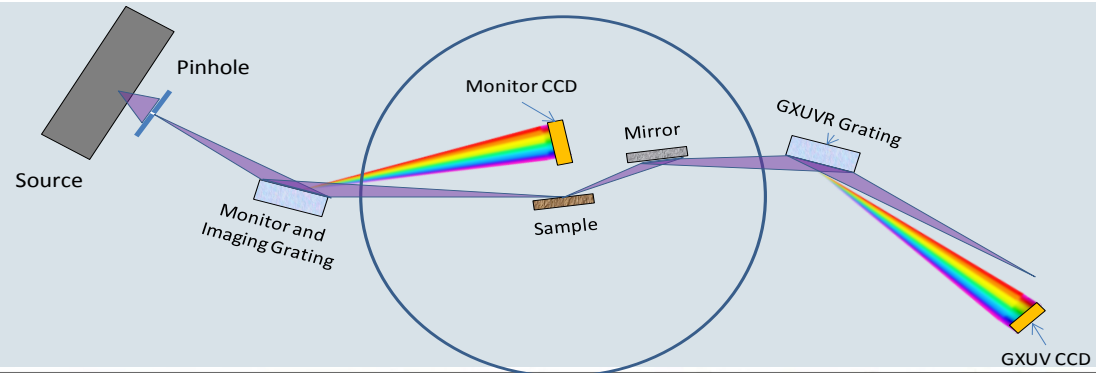


Table top R&D EUV Reflectometer „PANTER“

Top Level Task

R&D grade grazing incidence XUV reflectometry (GIXUVR) for arbitrary thin film analytics (e.g. NEXAFS)



Experimental Targets

AOI from 5-10: variable
(two angle measurement
→ calibration free)

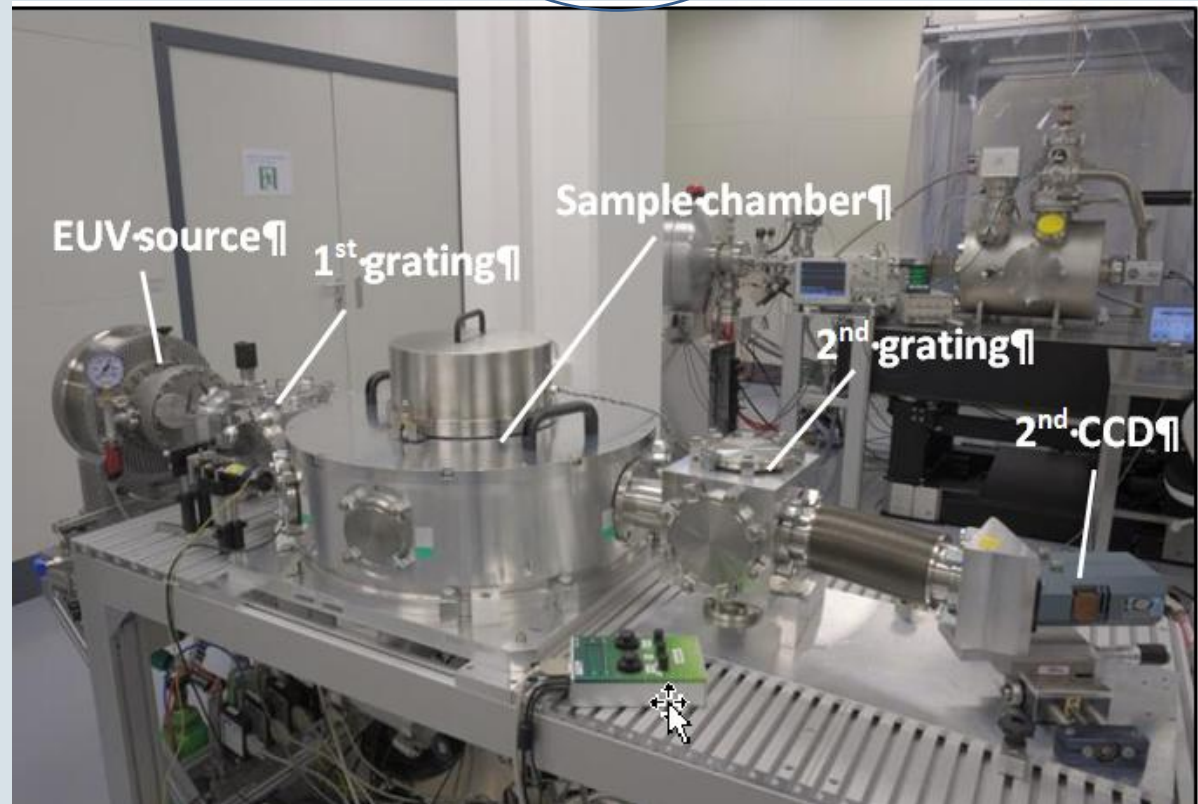
Spectral monitoring for GI !

Solving Concept

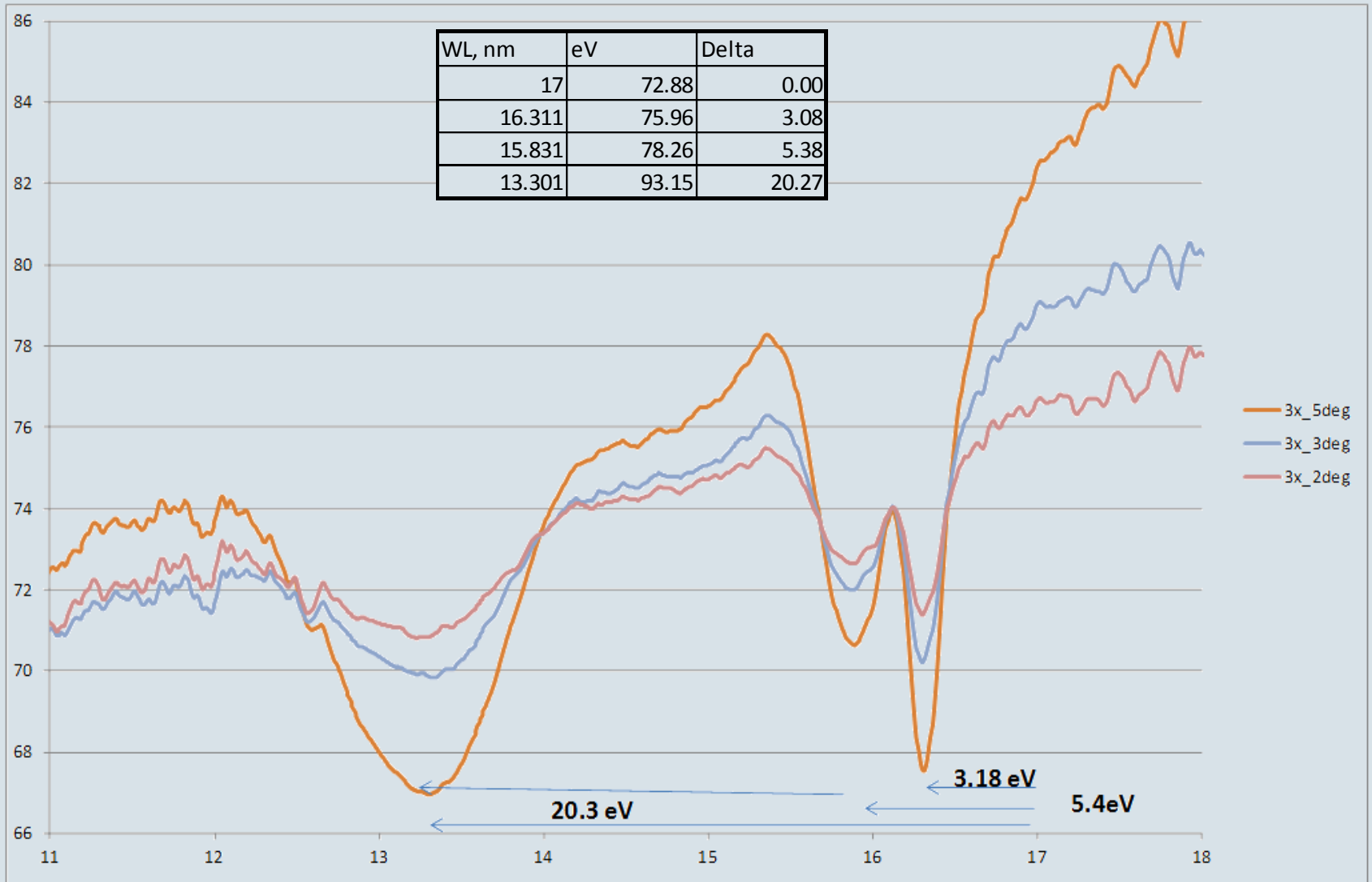
With "illumination grating" reference spectrum is out-coupled from 1st order.

AOI variation is compensated by deflection mirrors.

Medium Power standard EUV-lamp



→ Path to XUV-Analytics (XANES, NEXAFS), e.g.: Al₂O₃: Chemical shift due to amorphous or crystalline



EUV Resist: Interference Nano-patterning

Top Level Task

Print nanostructures of < 100 nm HP

Experimental Targets

Exploit "near field" polychromatic interference Lithography (Talbot)

Stable position during exposure

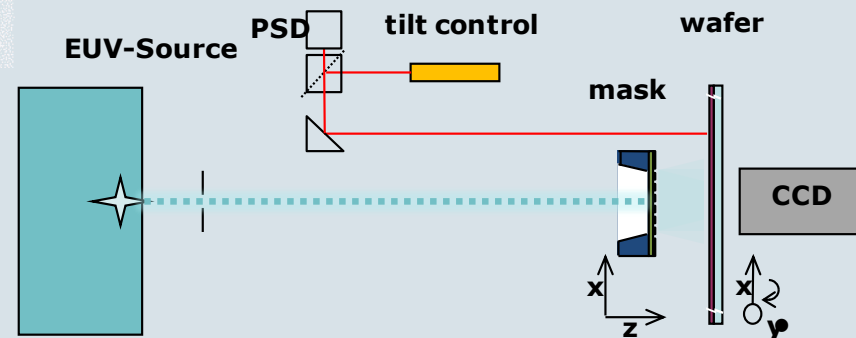
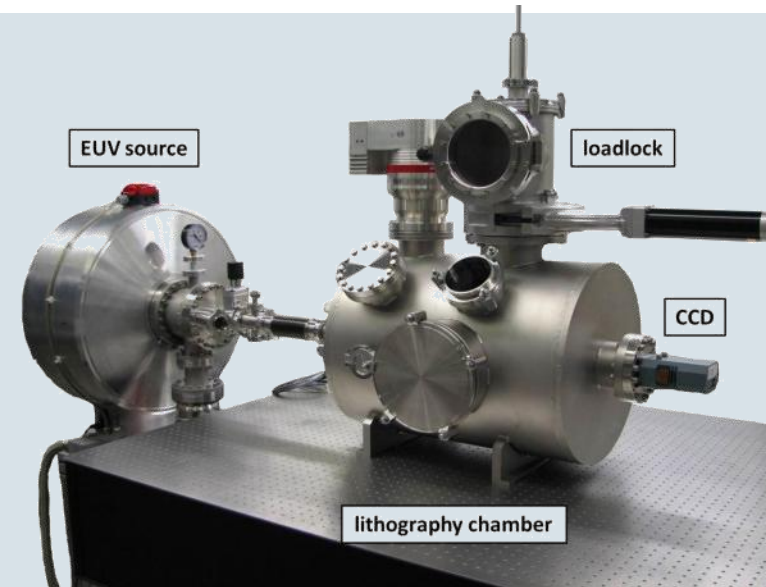
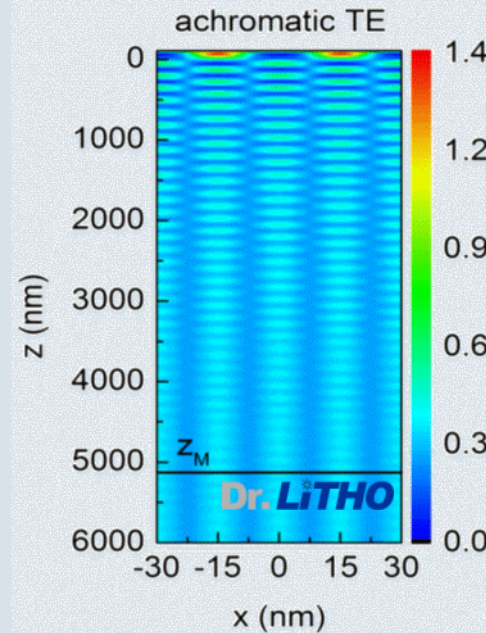
Precise mask-wafer distance

Solving Concept

Tight (< 100 nm) mask-wafer distance and tilt control.

High brightness & high flux DPP EUV source V4

11 nm emission optimized for high brightness



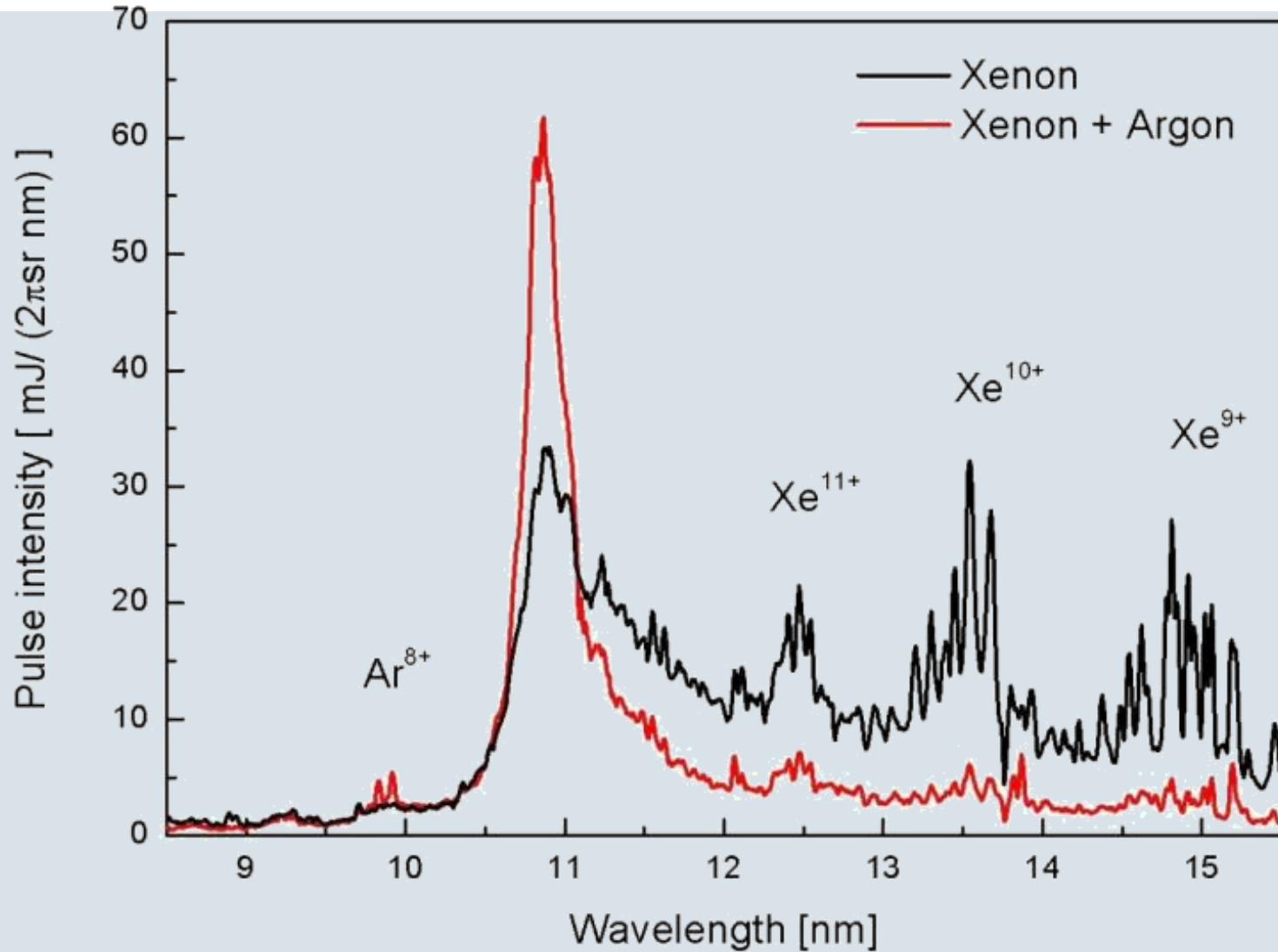
Exposure tool: Up to 100 mm wafers; fields of 4 mm^2

Printed in < 60 s @ 30 mJ/cm^2 ;

Control: Distance better 100 nm; Dose $< 0.1 \text{ mJ/cm}^2$

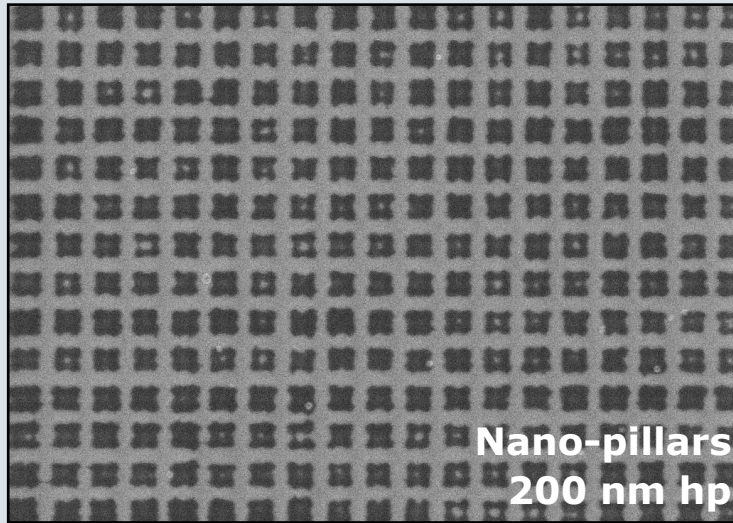
Outlook: Vector simulations show scalability down to **7.5 nm hp on wafer** with polarized light.

Special Solution: Xenon EUV Source tuned for narrowband 11 nm emission

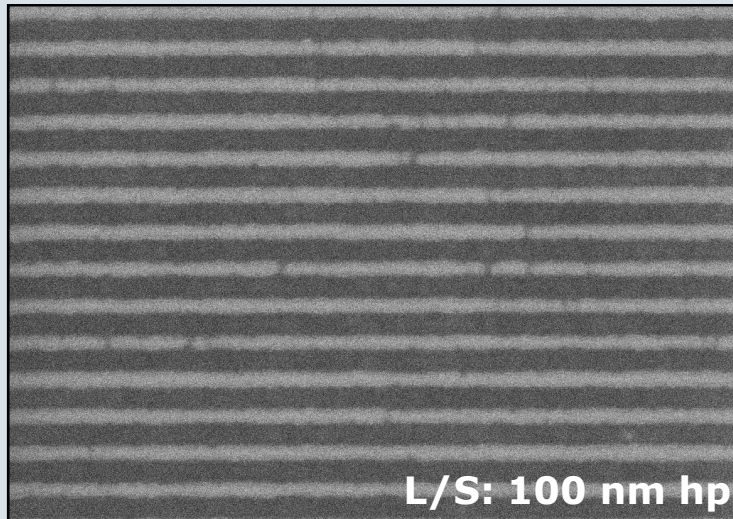
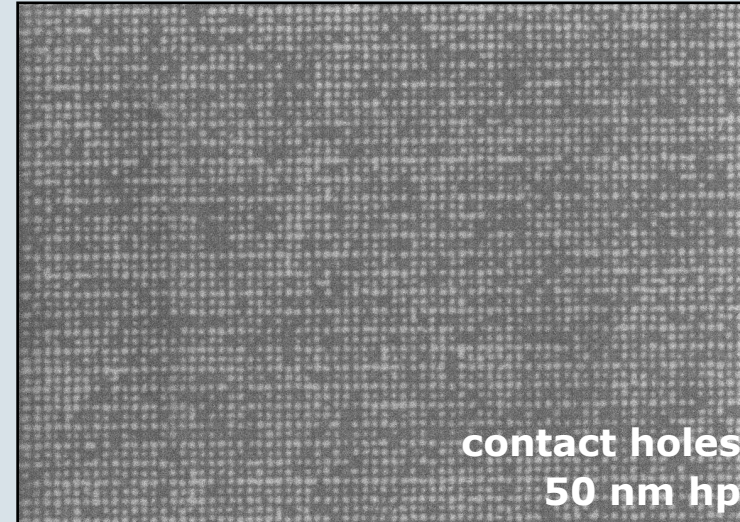


EUV source: Diameter ~250 μm; Brilliance: >100 W/(mm²sr)

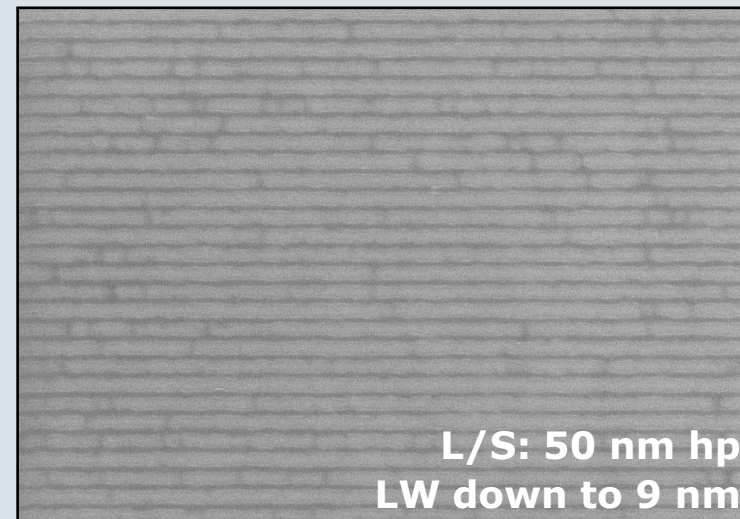
Lithography Exposure Results



*Proximity
printing
with
double
patterning*



*Demagnification
with
Talbot
lithography*



All shown exposures are produced in ~30nm thick ZEP520A resist

Top Level Target

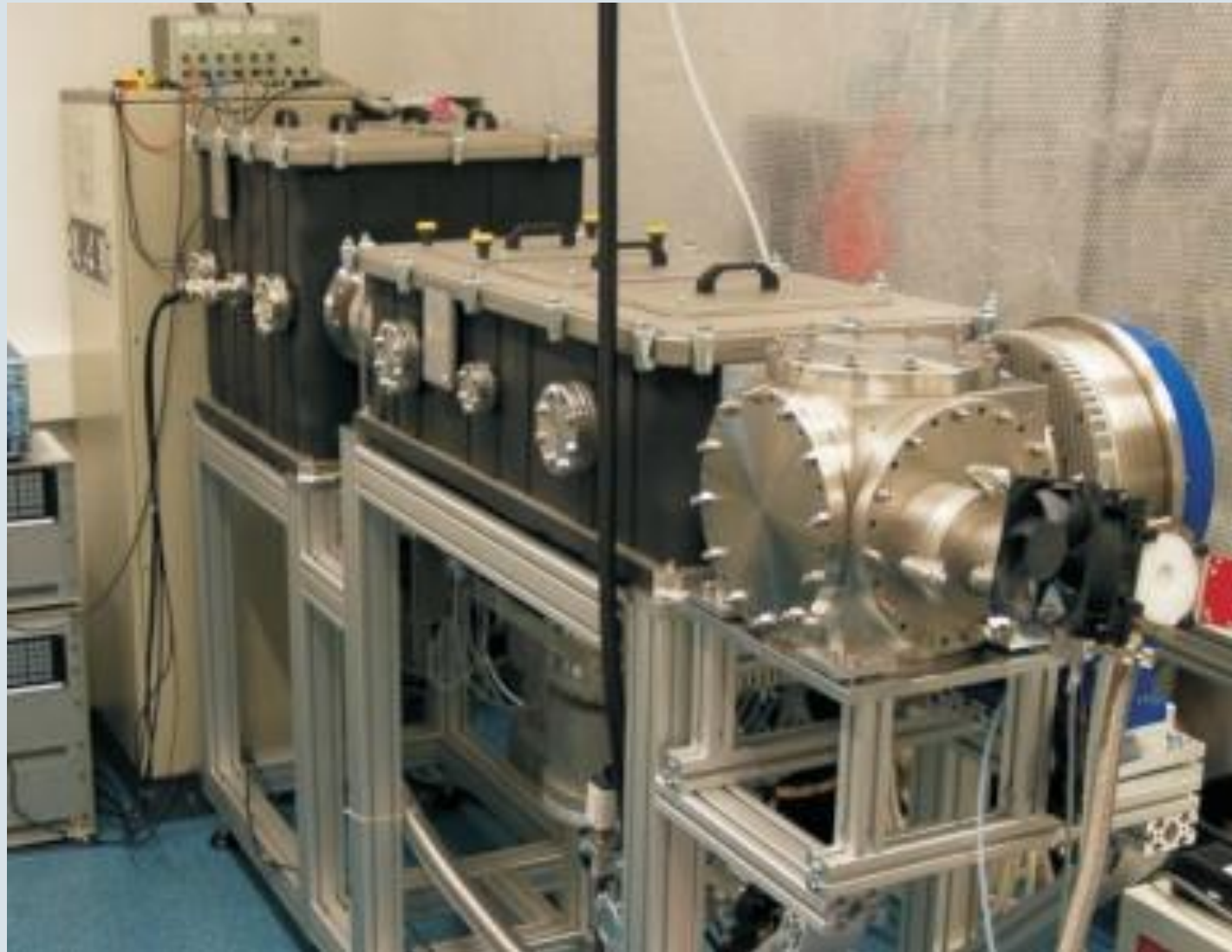
Quantify and Qualify
flare due to scatter
from multilayer
roughness (actinic)

Experimental Tasks

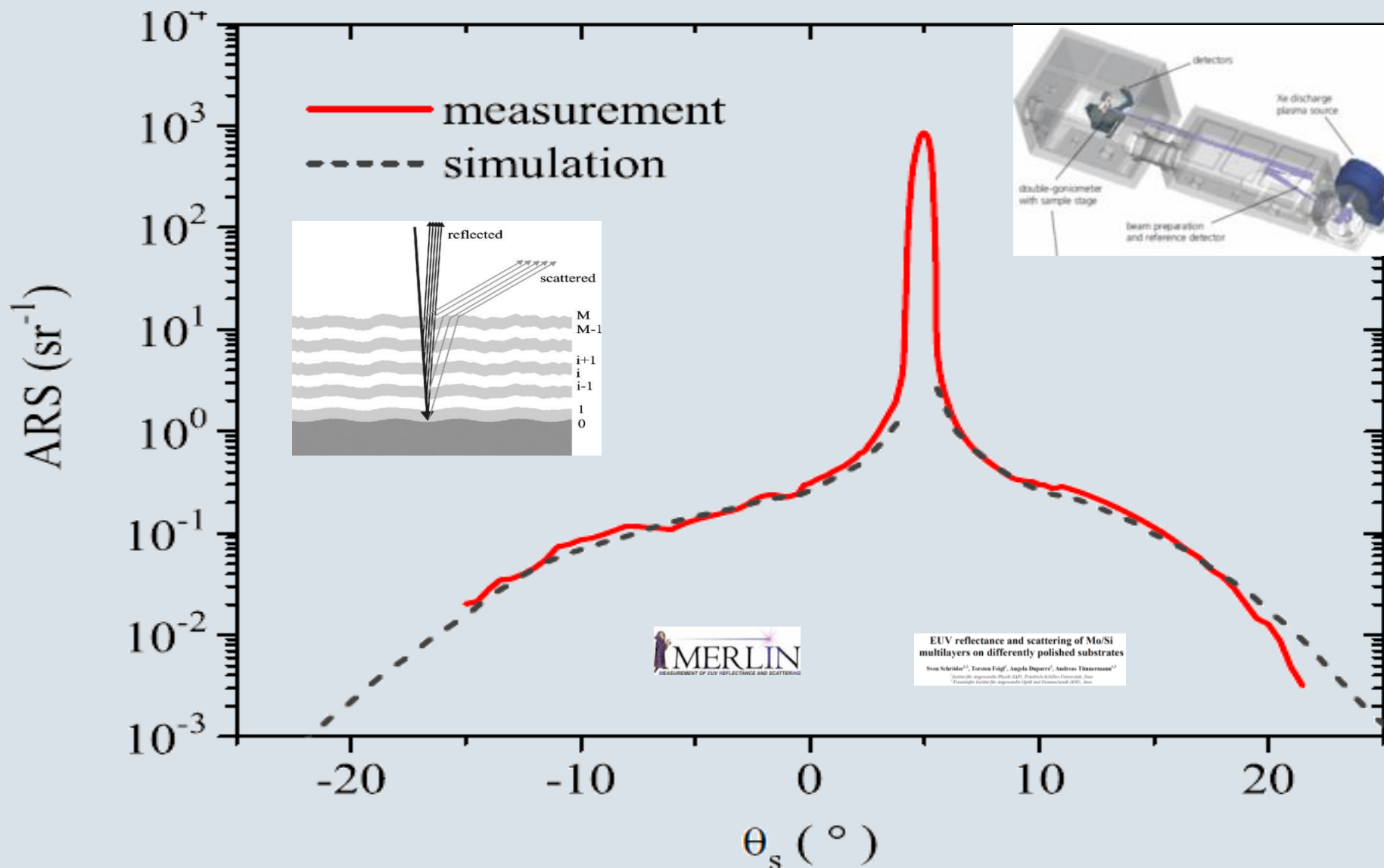
Spectral filtered and
flare clean irradiation
on small spot.
Sensitive wide angle
detection

Concept & Source

Medium power DPP
Source
SPF+ML reflection for
beam forming and
cleaning
Beam Monitor



Instrument for the Measuring of EUV Reflectance and Scattering - MERLIN



“Monochromatic ” general Scatterometry: Wide Angle XUV GI Scatterometry

Top Level Target

Collect scatter information from arbitrary nano structures for qualification of samples (wafers, masks)

Experimental Tasks

Find best compromise between resolution, wavelength, angle of incidence and number of orders.

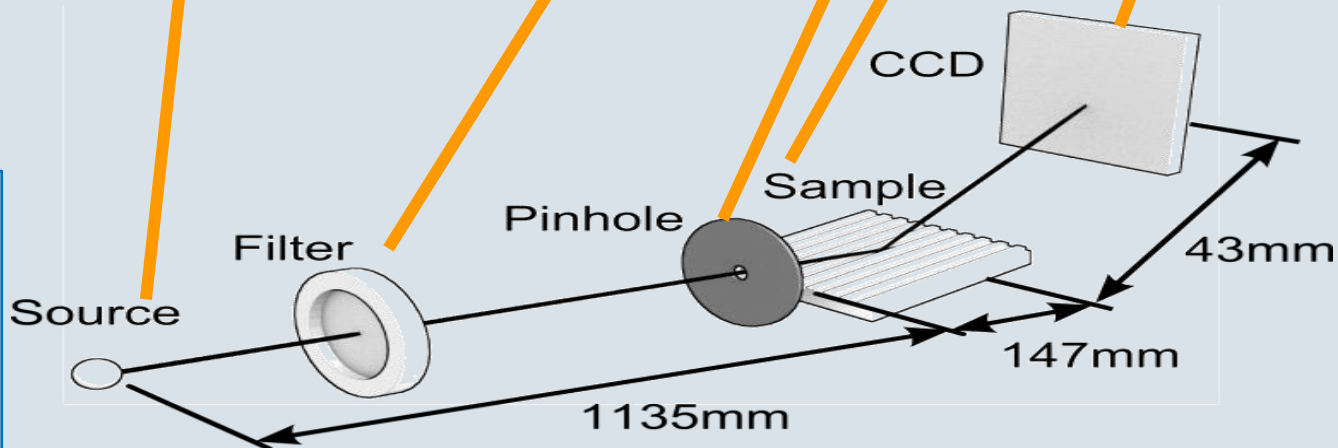
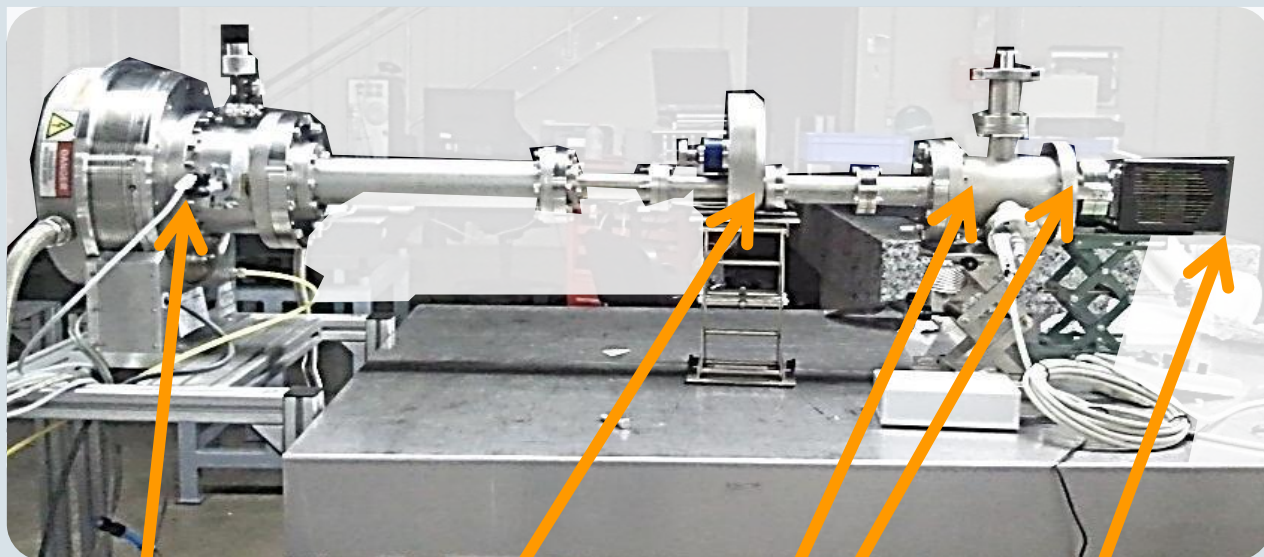
Generate quasi point like, monochromatic irradiation

Solving Solutions

Low power DPP or LPP source spectrally filtered for narrowband and spatially for low divergence.

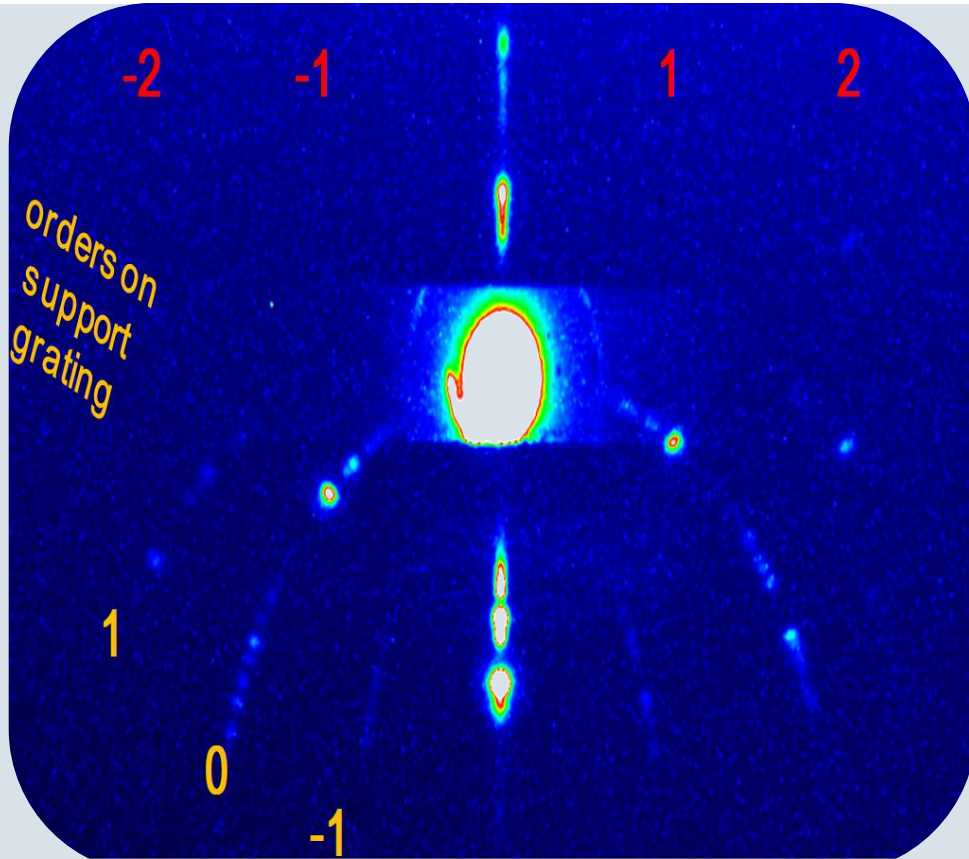
Clean collimated beam

Finite angles ($> 5^\circ$)

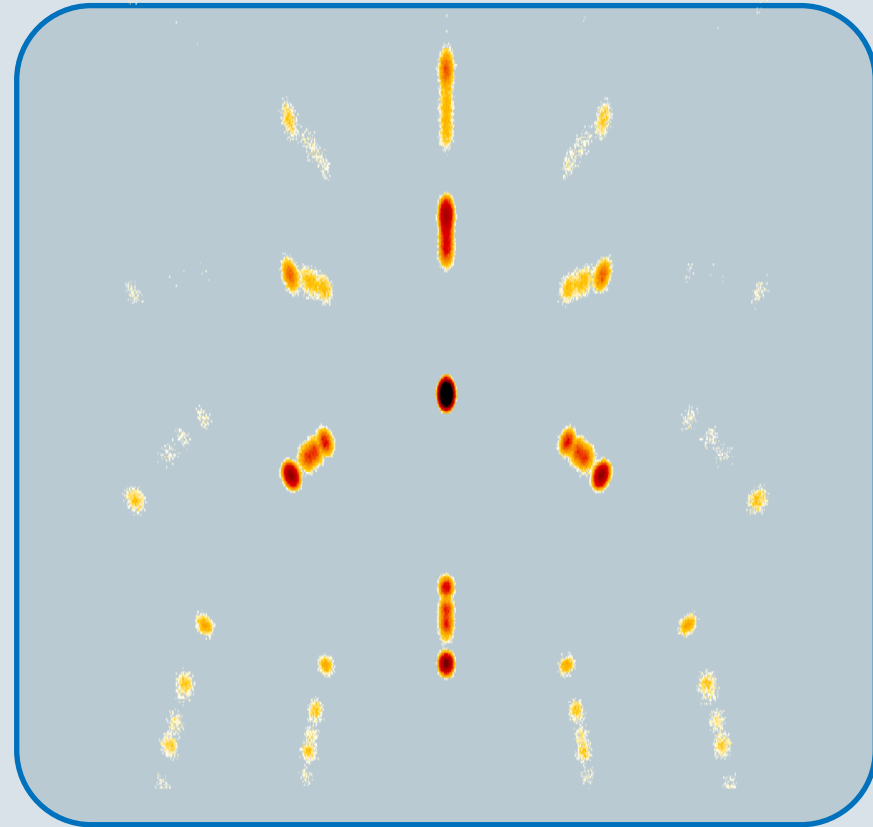


Straight forward compact Proof of feasibility experiment set-up with available lab components at BASC.

CD-WA-XUV-Scatterometry: First results



Typical Result obtained with PoP set-up



Simulation of expected result is in agreement

< 1mm² spot >5° AOI exp.< 10 s per image No beam stop
Spectral distribution exploits flexibility of EUV-Lamp with different working gases

→ Achieved: Accuracy of CD < ± 2 nm Reproducibility. < 0.06 nm rms < 0.2 nm PV

Actinic CD on masks is straight forward solvable task. Demand ? Specs ?

Nanoscopy (Here Soft-X-Ray)



Top-Level Target

Microscopy with
sub-20 nm resolution;
Soft-X or EUV

German Research Network

(Coordinator: Bruker ASC)

- High brightness LPP and DPP sources
- Grazing incidence, multilayer, and diffractive (zone plate) optics
- Tomography, Cryo

Experimental Tasks

Narrowband emission

$$\lambda/\Delta\lambda < 100$$

High brightness

(→ 100 W/mm²/sr)

Source Size matched

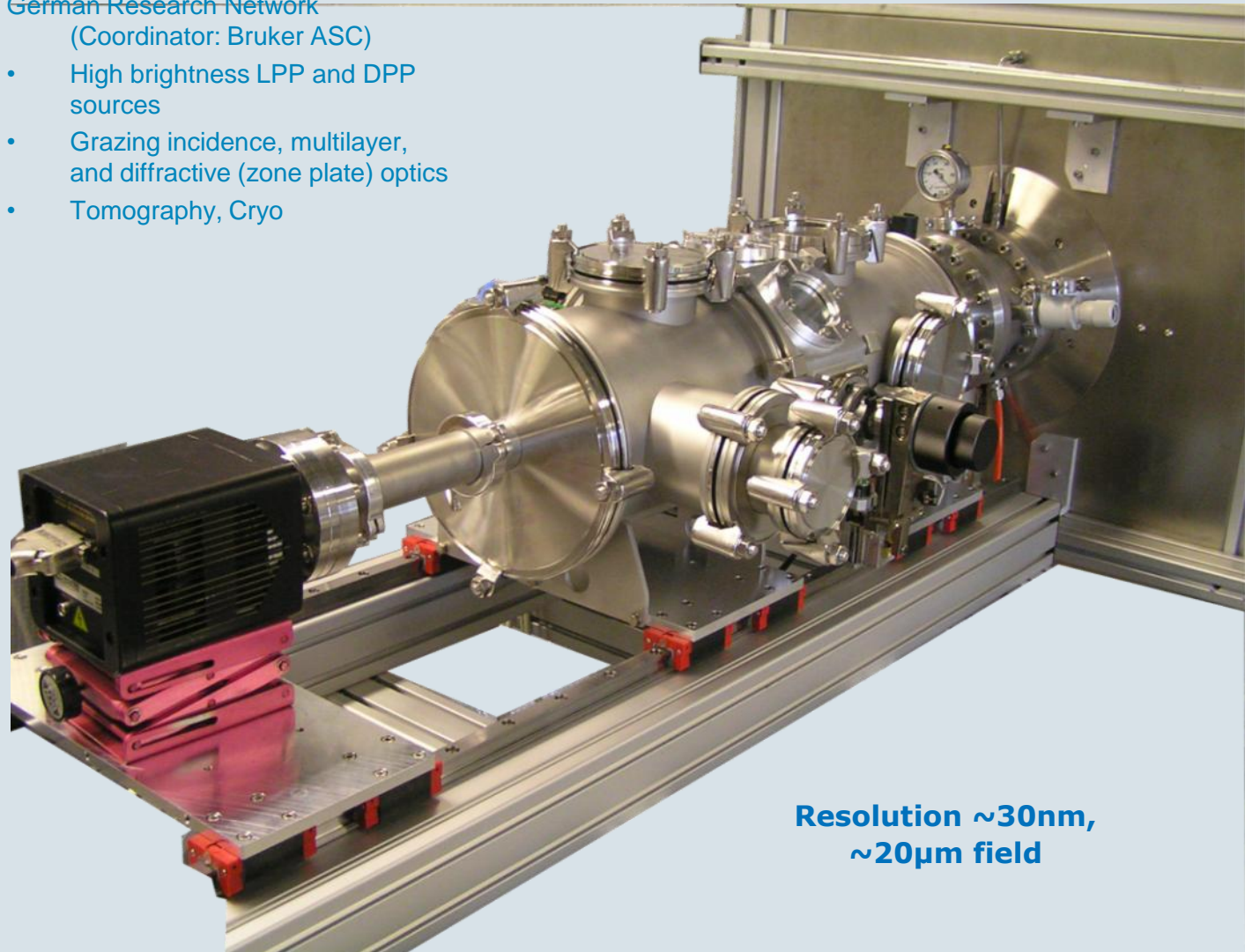
Solution Concept

Single Line optimized

DPP or LPP source

GI-Collector

Zone plate optics

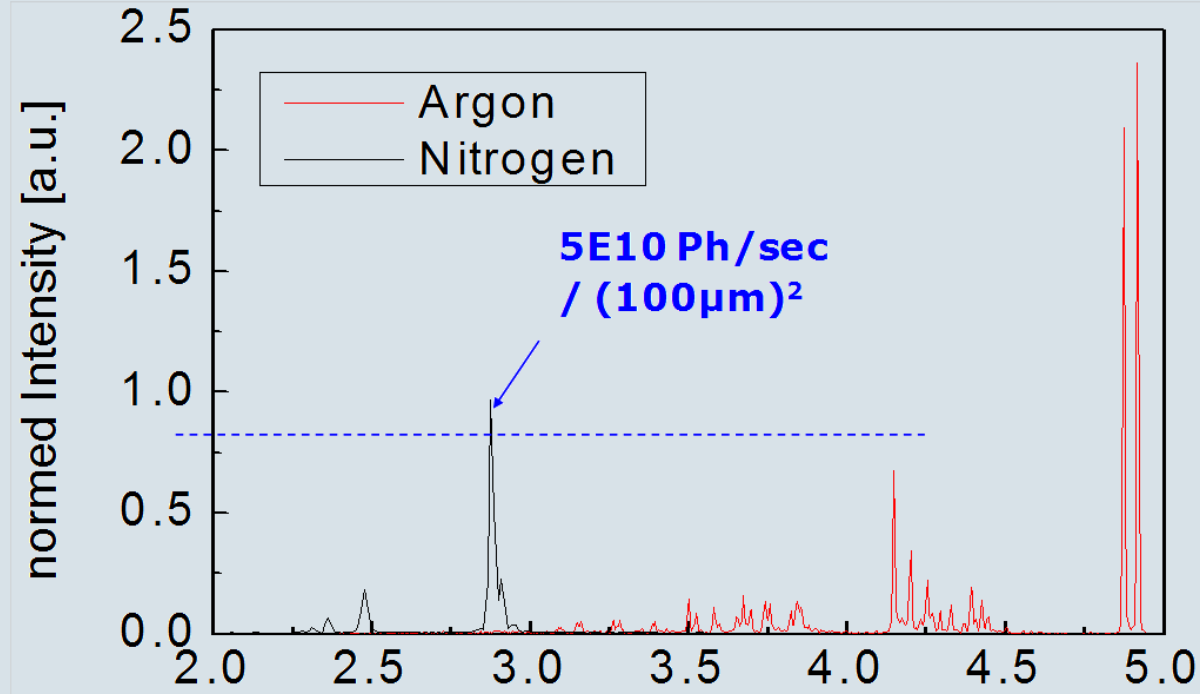


**Resolution ~30nm,
~20µm field**

Special Development: High Brightness Monochromatic XUV Source in Water Window

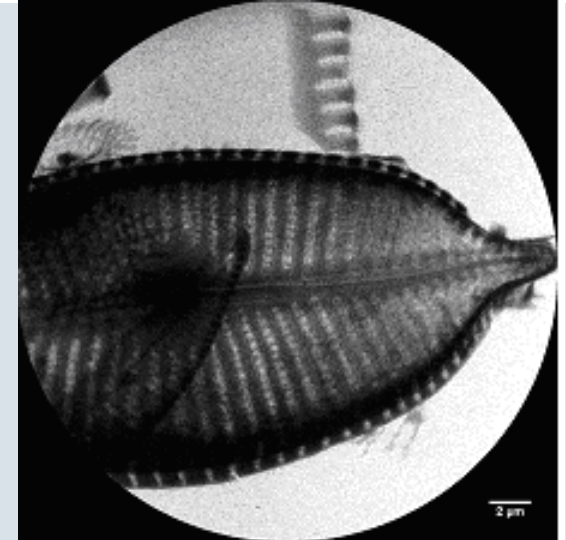
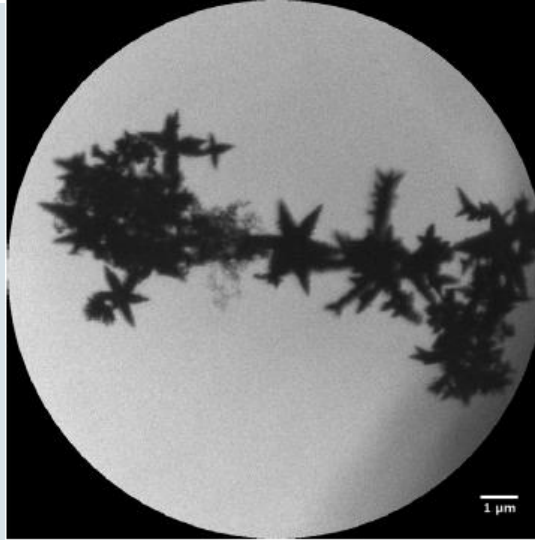
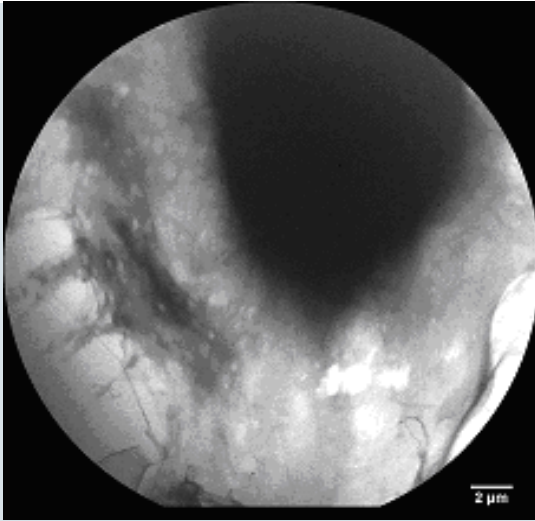


Benk et al., Optics Letters 33 (2008)

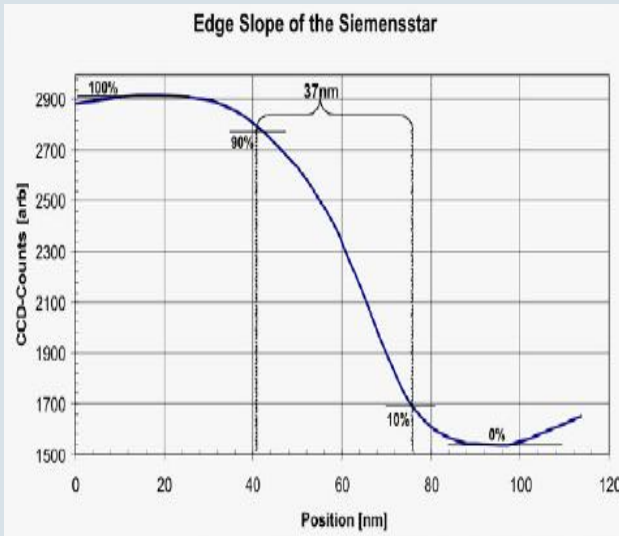


- el. Pulse energy : 12 - 20 J
- Repetition rate : 1- 2 kHz
- Peak current : 15 kA
- Input power : 10 - 20 kW
- source diameter : several 100 μm FWHM
- photon flux : $> 10^{14} \text{ Ph}/(2\pi \text{ sr})/ \text{ Pulse}$
: $> 4.6 \text{ W}/(2\pi \text{ sr}) @ 10 \text{ kW}$

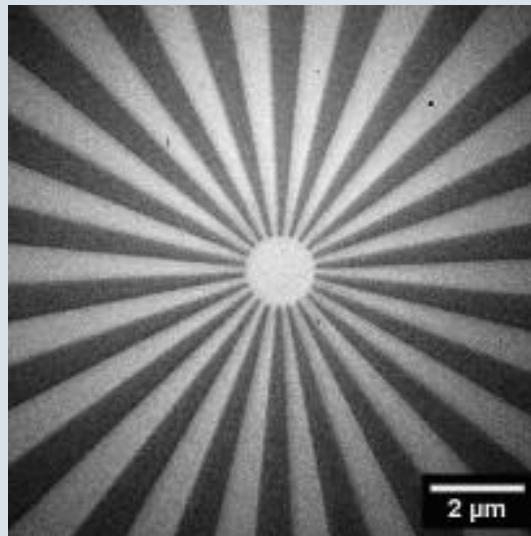
X-Ray Microscopy with DPP source: 40 nm Rayleigh Resolution demonstrated



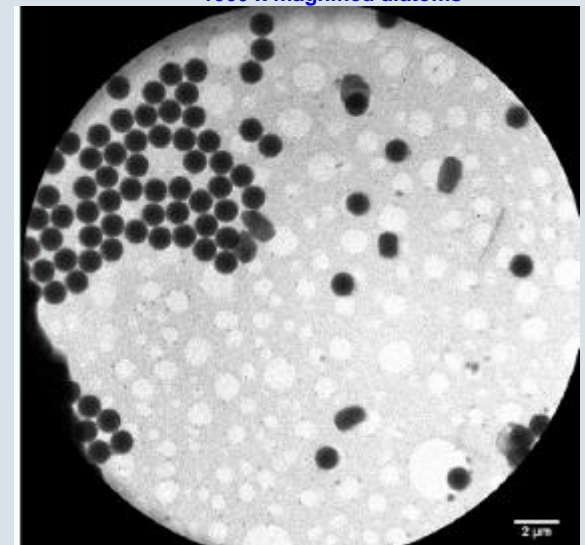
1000 x magnified diatoms



M. Benk, K. Bergmann, D. Schäfer (2008)



M. Benk, K. Bergmann, D. Schäfer (2007)



1000 x magnified diatoms and 80 nm latex spheres

EUV Mask: Actinic Blank Defect Inspection

R&D Grade ABIT in Operation

Top Level Target

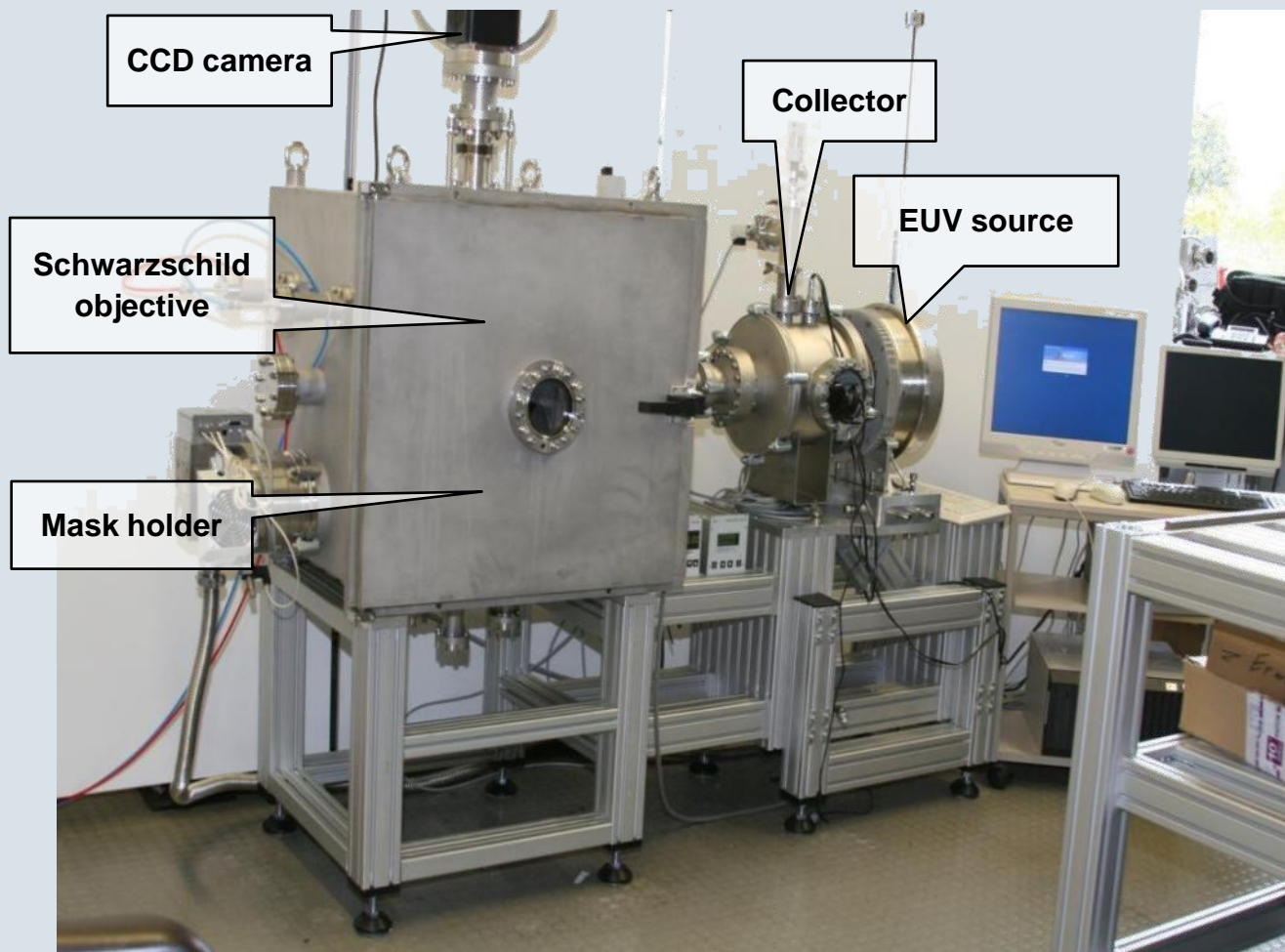
Find all printing defects of
> x nm on mask blanks.
Also purely actinic
(Phase)

Experimental Tasks

100 μ W irradiated on
sample spot of 1*1 mm²
Spectrally and flare clean
irradiation
High contrast of defect
signal and sample flare
(ML roughness !)

Solving Concept

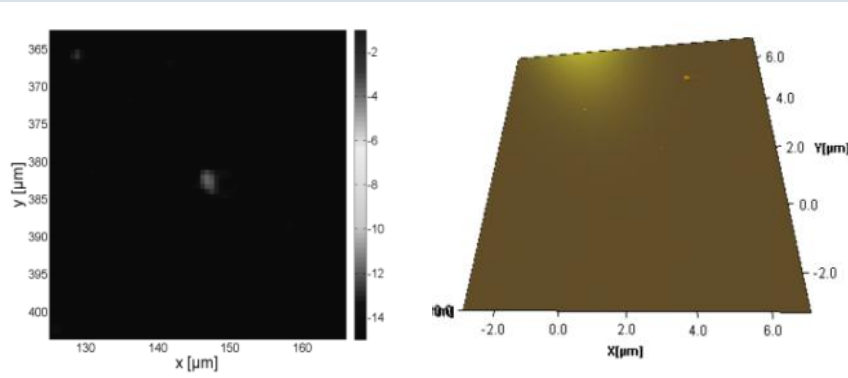
Dark field EUV
microscope
DPP EUV-Source
Filtered, magnified ,
homogen. irradiation
Large scatter collection
angle



Investigation results: Natural defects on a multilayer mirror

EUV

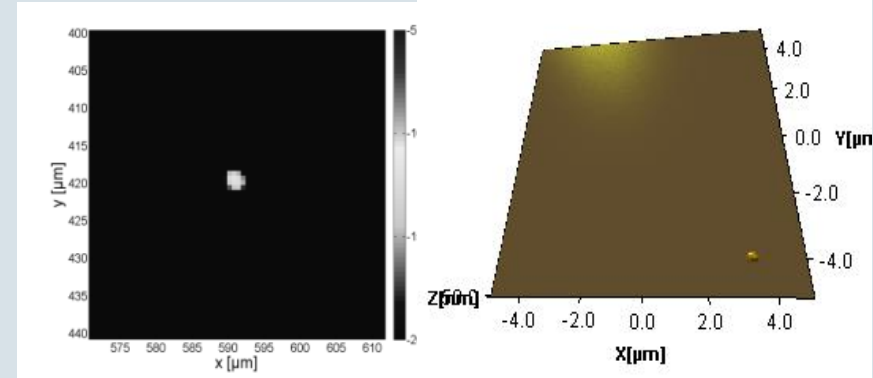
AFM



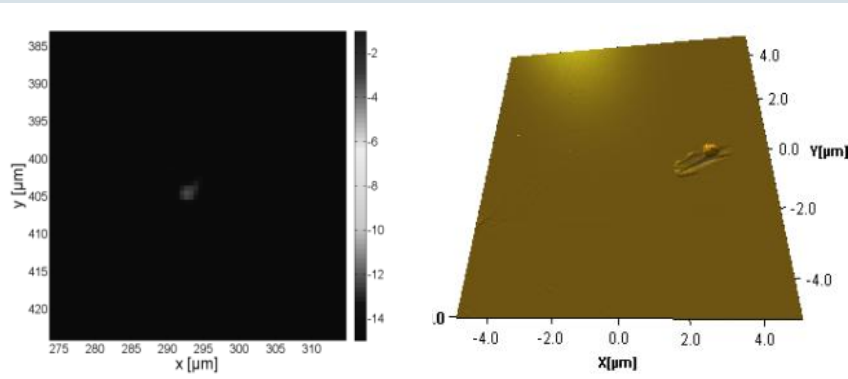
Bump:
Sphere: 220nm
Circle: 250 nm
Height: 160 nm

EUV

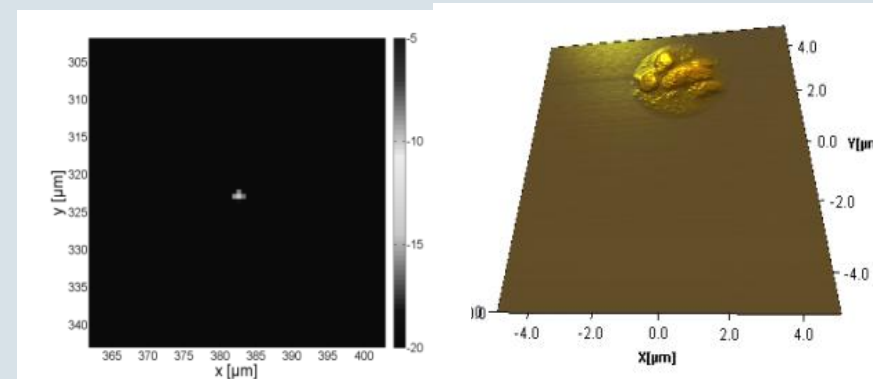
AFM



Potential phase defect



Sphere: 81 nm
Circle: 133 nm
Height: 25 nm



Sphere: 720 nm
Circle: 1220 nm
Height: 210 nm

- **Available LPP and DPP Lab sources support a broad range of laboratory based experiments and tooling.**
- **Most applications relate to actinic mask, optics, pellicle and resist testing, characterization and metrology in EUVL arena .**
However, also new options for nanoscopy, nano-printing, thin film analysis are supported.
- **Viable solutions are found in concept studies by selecting, adapting and tailoring effective Lab source, matched optical concept and suited components for vacuum, handling, detection and monitoring.**
- **Proof of concept experiments in our application labs allow to extrapolate to customer tailored solutions.**
- **Experience in UHV; optics, mechanics, automation, and control design, manufacturing and commissioning allows for offering, up to turn key installations**
- **→ One of a kind realization, is our business and very typical for our accelerator and beamline photon instrumentation contracts.**

Thank you for your attention

See you at Poster P 32

We gratefully acknowledge
Collaboration with PTB, xOptFab, Rhein-Ahr Campus Remagen, Helmholtz
and MBI Berlin

We also appreciate funding from the BMBF/Catrene (13N10572, CT301),
JARA-FIT, NRW (w1001nm016 a,b) and BMBF/ECSEL (16ESE0048).

www.research-instruments.de

From ACCEL and AIXUV to RI



1993-2007: ACCEL grew to Leading Global Accelerator Equipment and Systems Supplier

Accelerator Technology

- Linear Accelerators
- Special Manufacturing
- Insertion Devices

Magnet Technology

- Superconducting Magnets
- Synchrotrons/Cyclotrons
- Proton Therapy Systems

V: Beamline, X-Ray Optics

- Beamline Components,
- X-ray Optics,
- Endstations, UHV



2007 Varian Medical Systems acquires all Accele



2010 Varian cont. only Proton Therapy



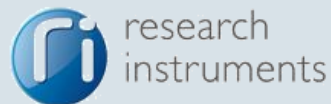
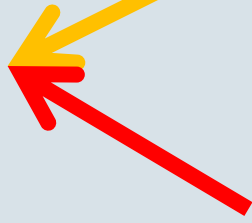
2010 BASC acq. AIXUV



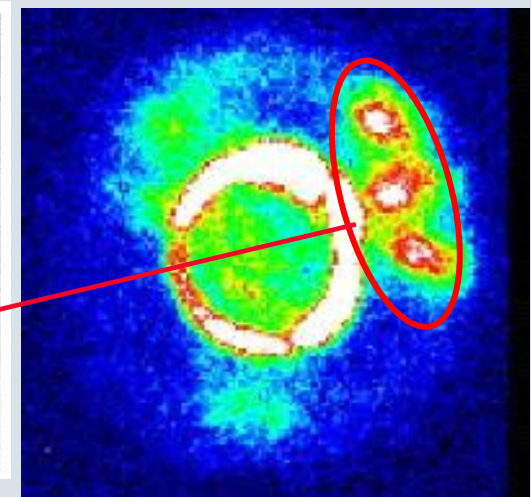
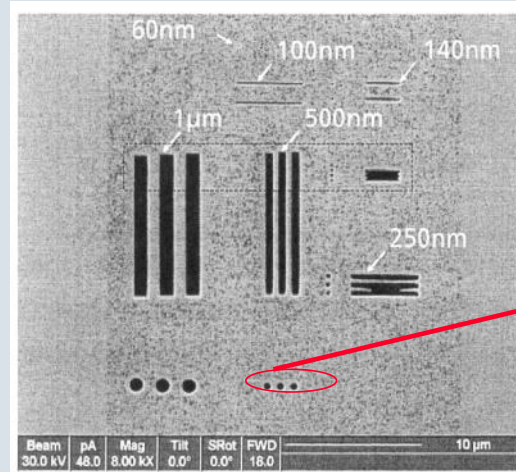
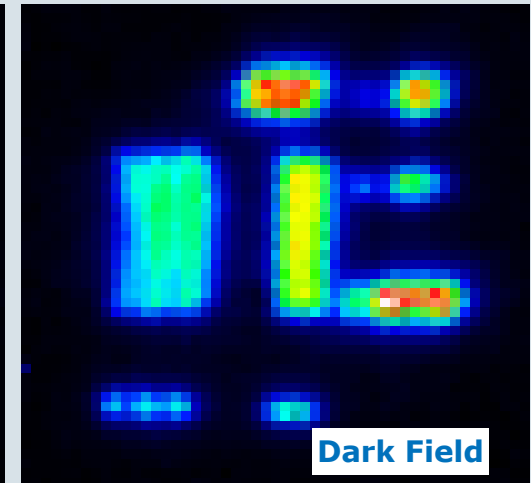
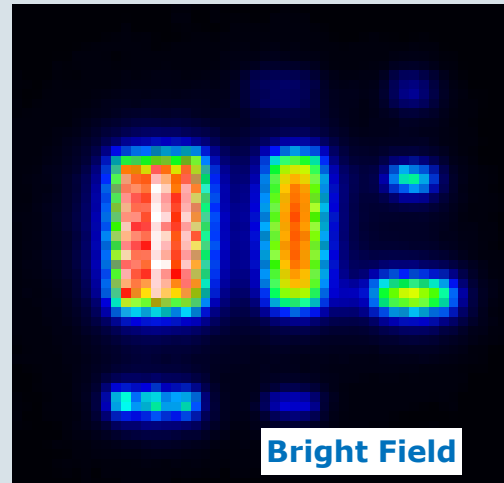
2013 BASC closes M part



2015 RI and BASC-V "re-merge"

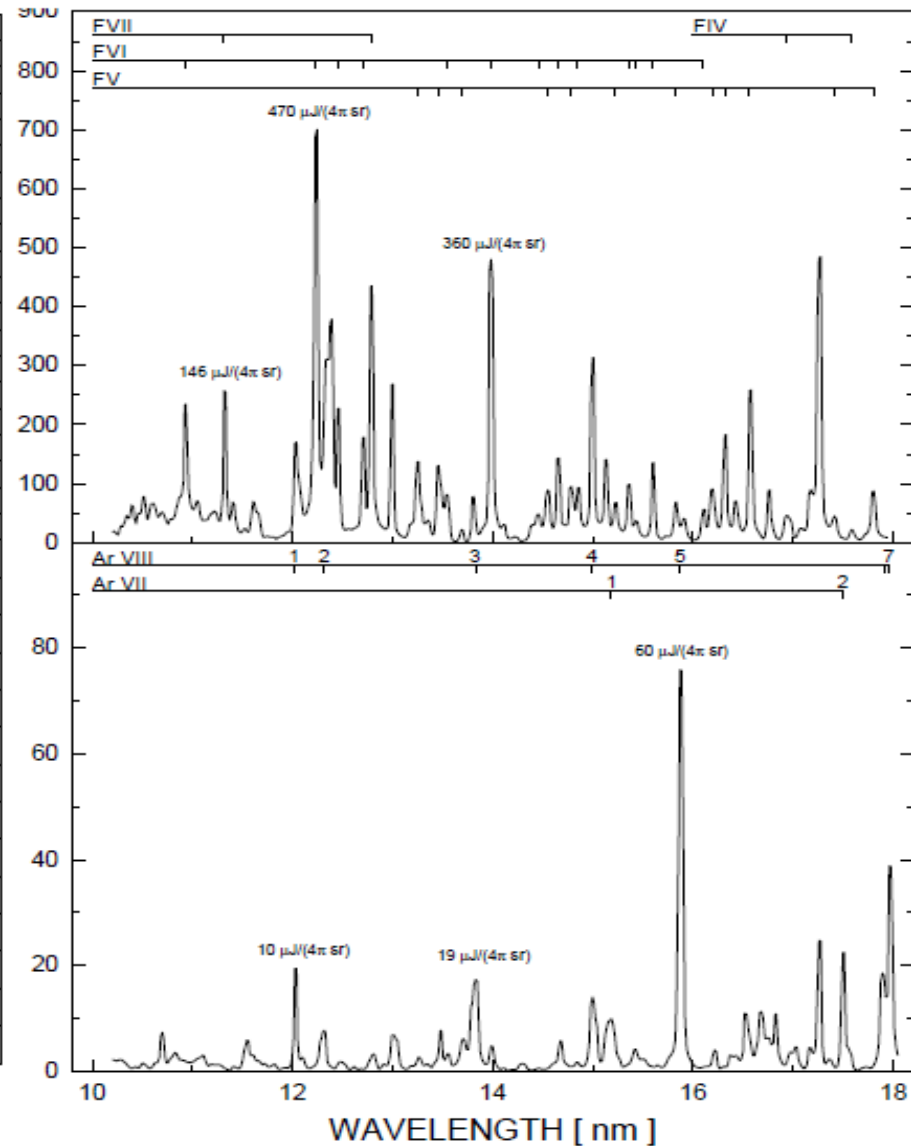
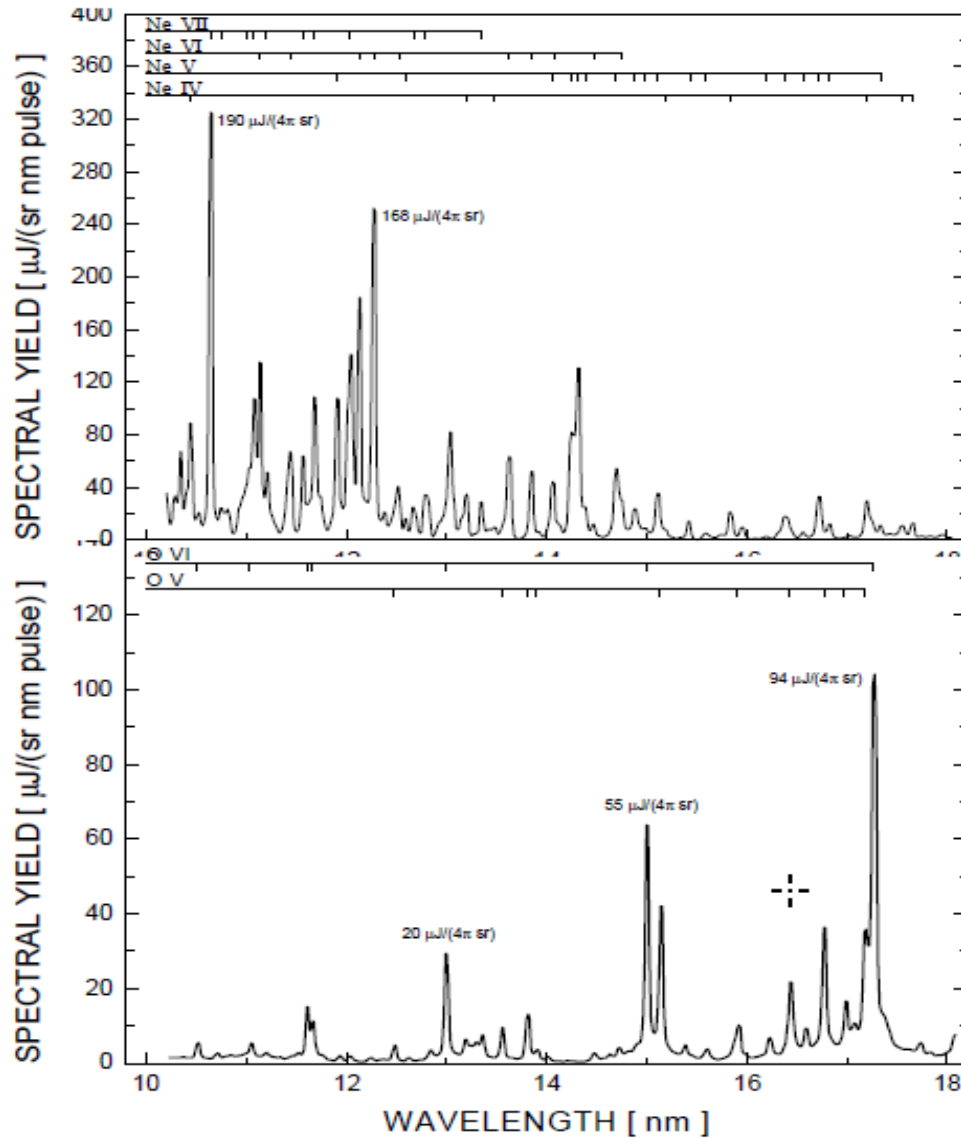


Actinic EUV Microscopy with DPP EUV-Lamp



“Three Points” of transmission mask
dist = 100 nm, W = 100 nm, mag = 224

Spectral Flexibility of EUV-Lamp: just change gas !



At field installed sources, we can supply lifetime monitoring of discharge and operation properties with

- 5 datasets per second for fast parameters and variables
- 1 set every 2 seconds for environmental parameters
- supported by event and error logging.

